Document Number: MMA52xxKW

Rev. 9, 03/2012

√RoHS



PSI5 Inertial Sensor

The MMA52xxKW family, a SafeAssure solution, includes the AKLV27 and PSI5 Version 1.3 compatible overdamped X-axis satellite accelerometers.

Features

- ±60g to ±480g Full-Scale Range
- Selectable 400 Hz, 3 Pole, or 4 pole Low-Pass Filter
- Single Pole High Pass Filter with Fast Startup and Output Rate Limiting
- PSI5 Version 1.3 Compatible
 - PSI5-P10P-500/3L Compatible
 - Programmable Time Slots with 0.5 μs Resolution
 - Selectable Baud Rate: 125 kBaud or 190.5 kBaud
 - Selectable Data Length: 8 or 10 bits
 - Selectable Error Detection: Even Parity, or 3-bit CRC
 - Optional Daisy Chain with External Low Side Switch
 - Two-Wire Programming Mode
- 16 μs Internal Sample Rate, with Interpolation to 1 μs
- · Pb-Free 16-Pin QFN, 6 by 6 Package
- Qualified AECQ100, Revision G, Grade 1 (-40°C to +125°C) (http://www.aecouncil.com/)

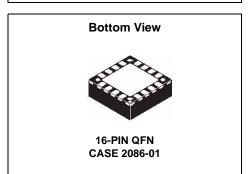
Typical Applications

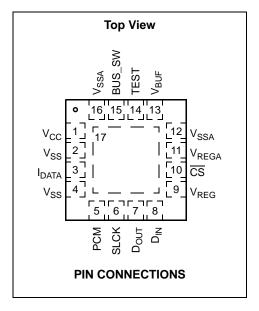
· Airbag Front and Side Crash Detection

	OR	DERING INFO	RMATION	
Device	Axis	Range	Package	Shipping
MMA5206KW	Х	60g	2086-01	Tubes
MMA5212KW	Х	120g	2086-01	Tubes
MMA5224KW	Х	240g	2086-01	Tubes
MMA5248KW	Х	480g	2086-01	Tubes
MMA5206KWR2	Х	60g	2086-01	Tape & Reel
MMA5212KWR2	Х	120g	2086-01	Tape & Reel
MMA5224KWR2	Х	240g	2086-01	Tape & Reel
MMA5248KWR2	Х	480g	2086-01	Tape & Reel

For user register array programming, please consult your Freescale representative.

MMA52xxKW







Application Diagram

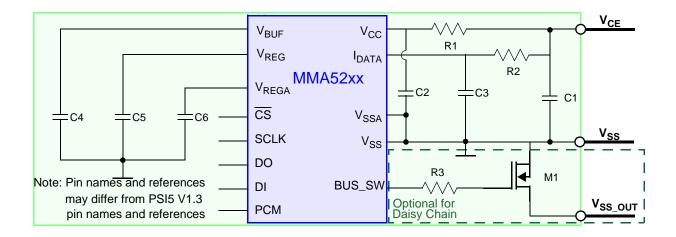


Figure 1. Application Diagram

		External Component Recomm	endations
Ref Des	Туре	Description	Purpose
C1	Ceramic	2.2 nF, 10%, 50V minimum, X7R	V _{CC} Power Supply Decoupling and Signal Damping
C3	Ceramic	470 pF, 10%, 50V minimum, X7R	I _{DATA} Filtering and Signal Damping
C2	Ceramic	15 nF, 10%, 50V minimum, X7R	V _{CC} Power Supply Decoupling
C4, C5, C6	Ceramic	1 μF, 10%, 10V minimum, X7R	Voltage Regulator Output Capacitor(s)
R1	General Purpose	82Ω, 5%, 200 PPM	V _{CC} Filtering and Signal Damping
R2	General Purpose	27Ω, 5%, 200 PPM	I _{DATA} Filtering and Signal Damping
R3	General Purpose	20 kΩ, 5%, 200 PPM	Gate Resistor for External Low Side Daisy Chain FET
M1	N-Channel MOSFET	_	Low Side Daisy Chain Transistor

Device Orientation

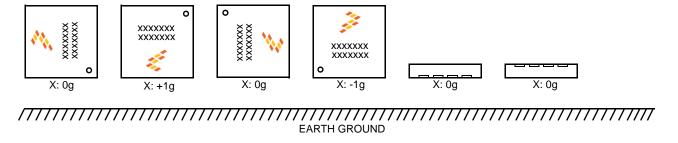


Figure 2. Device Orientation Diagram

Internal Block Diagram

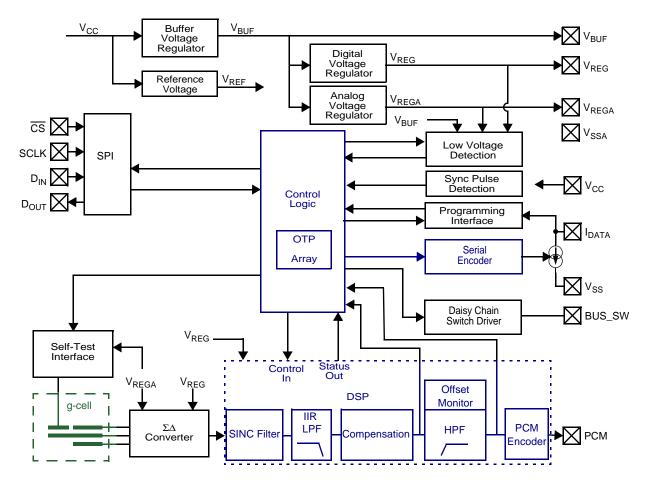


Figure 3. Block Diagram

1 Pin Connections

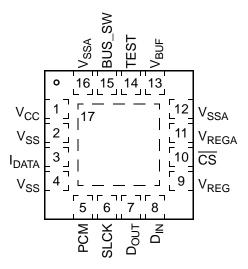


Figure 4. Top View, 16-Pin QFN Package

Table 1. Pin Description

Pin	Pin	Formal Name	Definition
	Name		
1	V _{CC}	Supply	This pin is connected to the PSI5 power and data line through a resistor and supplies power to the device. An external capacitor must be connected between this pin and V_{SS} . Reference Figure 1.
2	V _{SS}	Digital GND	This pin is the power supply return node for the digital circuitry.
3	I _{DATA}	Response Current	This pin is connected to the PSI5 power and data line through a resistor and modulates the response current for PSI5 communication. Reference Figure 1.
4	V _{SS}	Digital GND	This pin is the power supply return node for the digital circuitry.
5	PCM	PCM Output	This pin provides a 4 MHz PCM signal proportional to the acceleration data for test purposes. The output can be enabled via OTP. Reference Section 3.5.3.7. If unused, this pin must be left unconnected.
6	SCLK	SPI Clock	This input pin provides the serial clock to the SPI port for test purposes. An internal pulldown device is connected to this pin. This pin must be grounded or left unconnected in the application.
7	D _{OUT}	SPI Data Out	This pin functions as the serial data output from the SPI port for test purposes. This pin must be left unconnected in the application.
8	D _{IN}	SPI Data In	This pin functions as the serial data input to the SPI port for test purposes. An internal pulldown device is connected to this pin. This pin must be grounded or left unconnected in the application.
9	V _{REG}	Digital Supply	This pin is connected to the power supply for the internal digital circuitry. An external capacitor must be connected between this pin and V_{SS} . Reference Figure 1.
10	CS	Chip Select	This input pin provides the chip select to the SPI port for test purposes. An internal pullup device is connected to this pin. This pin must be left unconnected in the application.
11	V _{REGA}	Analog Supply	This pin is connected to the power supply for the internal analog circuitry. An external capacitor must be connected between this pin and V_{SSA} . Reference Figure 1.
12	VSSA	Analog GND	This pin is the power supply return node for the analog circuitry.
13	V _{BUF}	Power Supply	This pin is connected to a buffer regulator for the internal circuitry. The buffer regulator supplies both the analog (V_{REGA}) and digital (V_{REG}) supplies to provide immunity from EMC and supply dropouts on V_{CC} . An external capacitor must be connected between this pin and V_{SS} . Reference Figure 1.
14	TEST	Test Pin	This pin is must be grounded or left unconnected in the application.
15	BUS_SW	Bus Switch Gate Drive	This pin is the drive for a low side daisy chain switch. When daisy chain mode is enabled, this pin is connected to the gate of an n-channel FET which connects V _{SS} to V _{SS_OUT} . Reference Figure 1. If unused, this pin must be left unconnected.
16	VSSA	Analog GND	This pin is the power supply return node for the analog circuitry.
17	PAD	Die Attach Pad	This pin is the die attach flag, and is internally connected to VSS. Reference Section 6 for die attach pad connection details.
_	Corner Pads	Corner Pads	The corner pads are internally connected to V _{SS} .

MMA52xxKW

2 Electrical Characteristics

2.1 Maximum Ratings

Maximum ratings are the extreme limits to which the device can be exposed without permanently damaging it.

#	Rating	Symbol	Value	Unit	
1 2 3	Supply Voltage (V_{CC} , I_{DATA}) Reverse Current \leq 160 mA, t \leq 80 ms Continuous Transient ($<$ 10 μ s)	V _{CC_REV} V _{CC_MAX} V _{CC_TRANS}	-0.7 +20.0 +25.0	V V V	(3) (3) (9)
4	V _{BUF,} Test, BUS_SW		-0.3 to +4.2	V	(3)
5	V_{REG} , V_{REGA} , $SCLK$, \overline{CS} , D_{IN} , D_{OUT} , PCM		-0.3 to +3.0	V	(3)
6	Powered Shock (six sides, 0.5 ms duration)	9 _{pms}	±2000	g	(3)
7	Unpowered Shock (six sides, 0.5 ms duration)	g _{shock}	±2500	g	(3)
8	Drop Shock (to concrete, tile or steel surface, 10 drops, any orientation)	h _{DROP}	1.2	m	(5)
9 10 11 12	Electrostatic Discharge (per AEC-Q100) External Pins (V_{CC} , I_{DATA} , V_{SS} , V_{SSA}), HBM (100 pF, 1.5 k Ω) HBM (100 pF, 1.5 k Ω) CDM (R = 0 Ω) MM (200 pF, 0 Ω)	V _{ESD} V _{ESD} V _{ESD} V _{ESD}	±4000 ±2000 ±1500 ±200	V V V	(5) (5) (5) (5)
13 14	Temperature Range Storage Junction	T _{stg} T _J	-40 to +125 -40 to +150	°C °C	(3) (9)
15	Thermal Resistance	θJC	2.5	°C/W	(9, 14)

2.2 Operating Range

 $\label{eq:VL} \underline{V_L \leq (V_{CC} - V_{SS}) \leq V_H, \, T_L \leq T_A \leq T_H, \, \Delta T \leq 25 \, \, \text{K/min, unless otherwise specified.}}$

#	Characteristic Symbol Min		Тур	Max	Units		
16 17	Supply Voltage	V _{CC} V _{CC_UV}	V _L 4.2 V _{VCC_UV_F}		V _H 17.0 V _L	V	(1) (9)
18	Programming Voltage (I _{DATA} ≤ 85 mA) Applied to I _{DATA} , V _{CC}	V _{PP}	14.0	_	_	٧	(3)
19 20	Operating Temperature Range	T _A T _A	T _L -40 -40		T _H +105 +125	°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°°	(1) (3)

2.3 Electrical Characteristics - Supply and I/O $V_L \le (V_{CC} - V_{SS}) \le V_H, \ T_L \le T_A \le T_H, \ \Delta T \le 25 \ \text{K/min, unless otherwise specified.}$

#	Characteristic	Symbol	Min	Тур	Max	Units	
21	Quiescent Supply Current *	I _{IDLE}	4.0	_	8.0	mA	(1)
22	Modulation Supply Current *	I _{MOD}	I _{IDLE} + 22.0	I _{IDLE} + 26.0	I _{IDLE} + 30.0	mA	(1)
23	Inrush Current (Power On until V _{BUF} , V _{REG} , V _{REGA} Stable)	I _{INRUSH}	_	_	30	mA	(3)
24 25 26	Internally Regulated Voltages VBUF VREG VREGA *	V _{BUF} V _{REG} V _{REGA}	3.60 2.425 2.425	3.80 2.50 2.50	4.00 2.575 2.575	V V V	(1) (1) (1)
27 28 29 30	Low Voltage Detection Threshold V _{CC} Falling V _{BUF} Falling V _{REG} Falling V _{REGA} Falling Hysteresis	Vvcc_uv_f Vbuf_uv_f Vreg_uv_f Vrega_uv_f	3.40 2.95 2.15 2.15	3.70 3.15 2.25 2.25	4.0 3.35 2.35 2.35	V V V	(3, 6 (3, 6 (3, 6 (3, 6
31 32 33 34	V _{CC} V _{BUF} V _{REG} V _{REGA}	VCC_HYST VBUF_HYST VREG_HYST VREGA_HYST	0.10 0.05 0.05 0.05	0.25 0.10 0.10 0.10	0.40 0.15 0.15 0.15	V V V	(3) (3) (3) (3)
35 36	External Capacitor (V _{BUF} , V _{REG} , V _{REGA}) Capacitance ESR (including interconnect resistance)	ESR	500 0	1000 —	1500 200	nF mΩ	(9) (9)
37 38	Synchronization Pulse (Figure 5) V _{IDLE} Voltage Range * DC Sync Pulse Detection Threshold *	VIDLE ΔV _{SYNC}	— V _{IDLE} +1.4	UIDLE+2.0	15.4 V _{IDLE} +2.6	V V	(3, 11 (3, 6
39	Sync Pulse Pulldown Current	I _{SYNC_PD}	_	I _{MOD} - I _{IDLE}	_	mA	(3)
40	Output High Voltage (DO) I _{Load} = 100 µA	V _{OH}	V _{REG} - 0.1	_	_	V	(9)
41	Output Low Voltage (DO) I _{Load} = 100 μA	V _{OL}	_	_	0.1	V	(9)
42	Input High Voltage CS, SCLK, DI	V _{IH}	0.7 * V _{REG}	_	_	V	(9)
43	Input Low Voltage CS, SCLK, DI	V _{IL}	_	_	0.3 * V _{REG}	V	(9)
44 45	Input Current High (at V _{IH}) (DI) Low (at V _{IL}) (CS)	I _{IH} I _{IL}	-100 10	_	-10 100	μA μA	(9) (9)
46	Pulldown Resistance (SCLK)	R _{PD}	20	æ	100	kΩ	(9)
47 48	Temperature Monitoring Under-Temperature Monitor Threshold Over-Temperature Monitor Threshold	T _{IH} T _{IL}	 155	_	-55 —	°C ℃	(9) (9)
49	BUS_SW Output High Voltage (BUS_SW) I _{Load} = 100 μA	V _{BUS_SW_OH}	3.15	_	V_{BUF}	V	(9)
50	Output Low Voltage (BUS_SW) I _{Load} = 100 μA	V _{BUS_SW_OL}	0.0	_	0.45	V	(9)
51	Daisy Chain Addressing Mode Sync Pulse Period		_	t _{S-S_PM_L}	_	S	(7)
52	Bus Switch Output Activation Time (C = 50 pF) From last bit of "SetAdr" Response to 80% of V _{BUS_SW_OH}	tBUS_SW	_	_	300	μs	(7)
53	Sync Pulse Blanking Time after "SetAdr" Command Received From last bit of "SetAdr" Response	t _{DC_BLANKING}		200000 / f _{OSC}		s	(7)

2.4 Electrical Characteristics - Sensor And Signal Chain $V_L \leq (V_{CC} - V_{SS}) \leq V_H, \ T_L \leq T_A \leq T_H, \ \Delta T \leq 25 \ \text{K/min, unless otherwise specified.}$

#	Characteristic	Symbol	Min	Тур	Max	Units	
54 55 56 57	Sensitivity (10-bit output @ 100 Hz, referenced to 0 Hz) ±60g Range ±120g Range ±240g Range ±480g Range	SENS SENS SENS SENS	_ _ _ _	8 4 2 1	_ _ _ _	LSB/g LSB/g LSB/g LSB/g	(1) (1) (1) (1)
58 59 60 61 62 63	Total Sensitivity Error (including non-linearity) $ \begin{split} T_A &= 25^\circ C, \le \pm 240g \\ T_L &\le T_A \le T_H, \le \pm 240g, \ V_{VCC_UV_F} \le V_{CC} \le V_L \\ T_A &= 25^\circ C, \ \Rightarrow \pm 240g, \ T_L \le T_A \le T_H, \ \Rightarrow \pm 240g, \ T_L \le T_A \le T_H, \ \Rightarrow \pm 240g, \ V_{VCC_UV_F} \le V_{CC} \le V_L \end{split} $	ΔSENS_240 ΔSENS_240 ΔSENS_240 ΔSENS_480 ΔSENS_480 ΔSENS_480	-5 -7 -7 -5 -7	_ _ _ _ _	+5 +7 +7 +5 +7	% % % % %	(1) (1) (9) (1) (1) (9)
64 65	Digital Offset Before Offset Cancellation 10-bit 10-bit, $T_L \le T_A \le T_H$, $V_{VCC_UV_F} \le V_{CC} \le V_L$	OFF _{10Bit}	-52 -52	0	+52 +52	LSB LSB	(1) (9)
66 67	Digital Offset After Offset Cancellation 10-bit, 0.3 Hz HPF or 0.1 Hz HPF 10-bit, 0.04 Hz HPF	OFF _{10Bit}	-1 -2	0	+1 +2	LSB LSB	(1) (9)
68	Continuous Offset Monitor Limit 10-bit output, before compensation	OFF _{MON}	-66	_	+66	LSB	(3)
69	Range of Output (10-bit Mode) Acceleration	RANGE	-480	_	+480	LSB	(3)
70 71	Cross-Axis Sensitivity Z-axis to X-axis Y-axis to X-axis	V _{ZX}	-5 -5		+5 +5	% %	(3) (3)
72	System Output Noise Peak (10-bit Mode, 1 Hz - 1 kHz, All Ranges)	n _{Peak}	-4	_	+4	LSB	(3)
73	System Output Noise RMS (10-bit mode, 1 Hz - 1 kHz, All Ranges)	n _{RMS}	_	_	+1.0	LSB	(3)
74 75	Non-linearity 10-bit output, ≤ ±240g 10-bit output, > ±240g	NL _{OUT_240g} NL _{OUT_480g}	-2 -2	_ _	+2 +2	% %	(3) (3)

Electrical Characteristics - Self-Test and Overload 2.5

 $V_1 \le (V_{CC} - V_{SS}) \le V_H$, $T_1 \le T_A \le T_H$, $\Delta T \le 25$ K/min, unless otherwise specified.

#	Characteristic	Symbol	Min	Тур	Max	Units
76 77 78 79	10-Bit Output During Active Self-Test (T _L ≤ T _A ≤ T _H) ±60g Range ±120g Range ±240g Range ±480g Range	* 9ST10_60X * 9ST10_120X * 9ST10_240X * 9ST10_480X	120 40 56 8	_ _ _ _	280 160 184 112	LSB LSB LSB LSB
80	Acceleration (without hitting internal g-cell stops) ±60g Range Positive/Negative	g _{g-cell_Clip60X}	400	456	500	g
81	Acceleration (without hitting internal g-cell stops) ±120g Range Positive/Negative	g _{g-cell_Clip120X}	400	456	500	g
82	Acceleration (without hitting internal g-cell stops) ±240g Range Positive/Negative	gg-cell_Clip240X	1750	2065	2300	g
83	Acceleration (without hitting internal g-cell stops) ±480g Range Positive/Negative	g _{g-cell_Clip480X}	1750	2065	2300	g
84	ΣΔ and Sinc Filter Clipping Limit ±60g Range Positive/Negative	gADC_Clip60X	191	210	233	g
85	ΣΔ and Sinc Filter Clipping Limit ±120g Range Positive/Negative	9ADC_Clip120X	353	380	410	g
86	ΣΔ and Sinc Filter Clipping Limit ±240g Range Positive/Negative	9ADC_Clip240X	928	1055	1218	g
87	ΣΔ and Sinc Filter Clipping Limit ±480g Range Positive/Negative	9ADC_Clip480X	1690	1879	2106	g

MMA52xxKW

2.6 Dynamic Electrical Characteristics - PSI5 $V_L \le (V_{CC} - V_{SS}) \le V_H$, $T_L \le T_A \le T_H$, $\Delta T \le 25$ K/min, unless otherwise specified

#	Characteristic	Symbol	Min	Тур	Max	Units	
88 89 90 91 92 93 94 95 96 97 98 99 100 101 102	Initialization Timing Phase 1 Phase 2 (10-Bit, Synchronous Mode, k = 4) Phase 2 (8-Bit, Synchronous Mode, k = 8) Phase 2 (10-Bit, Asynchronous Mode 0, k = 8) Phase 2 (10-Bit, Asynchronous Mode 0, k = 16) Phase 3 (10-Bit, Synchronous Mode, ST_RPT = 0) Phase 3 (8-Bit, Synchronous Mode, ST_RPT = 0) Phase 3 (10-Bit, Asynchronous Mode 0, ST_RPT = 0) Phase 3 (8-Bit, Asynchronous Mode 0, ST_RPT = 0) Phase 3 (8-Bit, Asynchronous Mode 0, ST_RPT = 0) Offset Cancellation Stage 1 Operating Time Offset Cancellation Stage 2 Operating Time Self-Test Stage 1 Operating Time Self-Test Stage 3 Operating Time Self-Test Repetitions Programming Mode Entry Window	tpsis_init1 tpsis_init2_ss tpsis_init2_ss tpsis_init2_ss tpsis_init2_sa0 tpsis_init3_s0 tpsis_init3_ss tpsis_init3_sa0 tpsis_i		532000 / fosc 256 * ts-s 288 * ts-s 512 * tasync 576 * tasync 2 * ts-s 2 * ts-s 19 * tasync 320000 / fosc 128000 / fosc		5 5 5 5 5 5 5 5 5 5 5 5 5	(7) (7) (7) (7) (7, 12) (7, 12) (7, 12) (7, 12) (7) (7) (7) (7) (7, 12) (7)
104 105 106 107 108 109 110 111 112 113 114	Synchronization Pulse (Figure 5, Figure 28 and Figure 32) Reset to first sync pulse (Program Mode Entry) Reset to first sync pulse (Normal Mode) Sync Pulse Period Sync Pulse Width Sync Pulse Reference LPF time constant Sync Pulse Reference Discharge Start Time Sync Pulse Reference Discharge Activation Time Sync Pulse Detection Disable Time (BLANKTIME = 0) Analog Delay of Sync Pulse Detection Sync Pulse Pulldown Function Delay Time Sync Pulse Pulldown Function Activate Time Sync Pulse Detection Jitter	trs_pm trs trs ts-s ts-ync tsync_lpf tsync_lpf_rst_st tsync_lpf_rst tsync_off_500 ta_sync_dly tpd_oly tpd_on tsync_jit	58 tpsi5_init1 tsync_off 9 120	280 66 / fosc 616 / fosc 1810 / fosc 74 / fosc 64 / fosc		ms s μs μs s s s s s	(7) (7) (7) (7) (9) (7) (7) (7) (9) (7) (7)
116 117	Data Transmission Single Bit Time (PSI5 Low Bit Rate) Data Transmission Single Bit Time (PSI5 High Bit Rate) *	t _{BIT_LOW}	7.6000 4.9875	8.0000 5.2500	8.4000 5.5125	μs μs	(7) (7)
118 119	Modulation Current (20% to 80% of I _{MOD} - I _{IDLE}) Rise Time Fall Time	^t RISE ^t FALL	324 324	463 463	602 602	ns ns	(3) (3)
120 121	Position of bit transition (PSI5 Low Baud Rate) * Position of bit transition (PSI5 High Baud Rate) *	[†] Bittrans_LowBaud [†] Bittrans_HighBaud	49 47	50 æ	51 53	% %	(7) (7)
122	Asynchronous Response Time *	t _{ASYNC}	_	912 / f _{OSC}	æ	s	(7)
123 124 125 126 127 128 129 130	Time Slots Minimum Programmed Time Slot (TIMESLOTx = 0x001) Maximum Programmed Time Slot (TIMESLOTx = 0x3FF) Default Time Slot (TIMESLOTx = 0x000) Time Slot Resolution Sync Pulse to Daisy Chain Default Time Slot 1 Sync Pulse to Daisy Chain Default Time Slot 2 Sync Pulse to Daisy Chain Default Time Slot 3 Sync Pulse to Daisy Chain Programming Time Slot	tTIMESLOTX_MIN tTIMESLOTX_MAX tTIMESLOT_DFLT tTIMESLOT_DC1 tTIMESLOT_DC2 tTIMESLOT_DC3 tTIMESLOT_DCP		2 / f _{OSC} 2046 / f _{OSC} 186 / f _{OSC} 2 / f _{OSC} 186 / f _{OSC} 1400 / f _{OSC} 186 / f _{OSC}		s s s/LSB s s	(7, 9) (3, 7) (3, 7) (7) (7) (7) (7) (7)
131 132	Data Interpolation Latency (Figure 35, Figure 36) Data Setup Time - Synchronous Mode (Figure 36) Data Setup Time - Double Sample Rate Mode (Figure 37) Data Setup Time - 16-bit Resolution Mode (Figure 39)	tLAT_INTERP tDATASETUP_synch tDATASETUP_double tDATASETUP_16	64 / f _{OSC} 48 / f _{OSC} 48 / f _{OSC} 48 / f _{OSC}	_ _ _ _	65 / f _{OSC} 56 / f _{OSC} 60 / f _{OSC} 60 / f _{OSC}	\$ \$ \$ \$	(7) (7) (7) (7)
133 134 135 136 137	Programming Mode Timing Programming Mode Sync Pulse Period Programming Mode Command Timeout OTP Write Command to V _{CC} = V _{PP} OTP Write CMD Response to OTP programming start Time to program one OTP bit	ts-s_pm_l tpm_timeout tprog_hold tprog_delay tprog_bit	495 — — — 512	500 4 * t _{S-S_PM} — —	505 — 20 40 —	μs μs μs ms μs	(7) (7) (7) (7) (7) (7)

2.7 Dynamic Electrical Characteristics - Signal Chain $V_L \leq (V_{CC} - V_{SS}) \leq V_H, \ T_L \leq T_A \leq T_H, \ \Delta T \leq 25 \ \text{K/min, unless otherwise specified}$

#	Characteristic	Symbol	Min	Тур	Max	Units	
138	Internal Oscillator Frequency *	fosc	3.80	4	4.20	MHz	(1)
139 140 141 142	DSP Low-Pass Filter (Note15) Cutoff frequency LPF0 (referenced to 0 Hz) Filter Order LPF0 Cutoff frequency LPF1 (referenced to 0 Hz) Filter Order LPF1 *	f _{C_LPF0} O _{LPF0} f _{C_LPF1} O _{LPF1}	_ _ _ _	400 3 400 4	 	Hz 1 Hz 1	(7) (7) (7) (7)
143 144 145 146 147 148 149 150 151 152 153 154 155 156 157	DSP Offset Cancellation Low-Pass Filter (Note 15) Offset Cancellation Low-Pass Filter Input Sample Rate Stage 1 Cutoff frequency, Startup Phase 1 Stage 1 Filter Order, Startup Phase 1 Stage 2 Cutoff frequency, Startup Phase 1 Stage 2 Filter Order, Startup Phase 1 Cutoff frequency, Option 0 Filter Order, Option 0 Cutoff frequency, Option 1 Filter Order, Option 1 Cutoff frequency, Option 2 Filter Order, Option 2 Offset Cancellation Output Update Rate (8-Bit Mode) Offset Cancellation Output Step Size (8-Bit Mode) Offset Cancellation Output Step Size (10-Bit Mode) Offset Monitor Update Frequency Offset Monitor Count Limit Offset Monitor Counter Size	toc_sampleRate fc_OC10 OOC10 fc_OC03 OOC03 fc_OC0 OOC0 fc_OC1 OOC1 fc_OC2 OOC2 toffRate_8 OFFStep_8 toffRate_10 OFFMONOSC OFFMONCNTLIMIT OFFMONCNTSIZE		256 10.0 1 0.300 1 0.100 1 0.040 1 f _{OSC} / 2e6 0.125 f _{OSC} / 2e6 0.5 f _{OSC} /2000 4096 8192		μs Hz 1 Hz 1 Hz 1 S LSB S LSB Hz 1	(7) (7) (7) (7) (7) (7) (7) (7) (7) (7)
159 160 161 162	Sensing Element Natural Frequency ±60g ±120g ±240g ±480g	fgcell_X60 fgcell_X120 fgcell_X240 fgcell_X480	12651 12651 26000 26000	_ _ _	13871 13871 28700 28700	Hz Hz Hz Hz	(9) (9) (9) (9)
163 164 165 166	Sensing Element Rolloff Frequency (-3 db) ±60g ±120g ±240g ±480g	fgcell_X60 fgcell_X120 fgcell_X240 fgcell_X480	938 938 3952 3952	_ _ _ _	2592 2592 14370 14370	Hz Hz Hz Hz	(9) (9) (9) (9)
167 168 169 170	Sensing Element Damping Ratio ±60g ±120g ±240g ±480g	ζgcell_X60 Śgcell_X120 Śgcell_X240 Śgcell_X480	2.760 2.760 1.260 1.260	_ _ _ _	6.770 6.770 3.602 3.602	_ _ _	(9) (9) (9) (9)
171 172 173 174	Sensing Element Delay (@100 Hz)	fgcell_delay_X60 fgcell_delay_X120 fgcell_delay_X240 fgcell_delay_X240	63 63 13 13	_ _ _ _	170 170 40 40	μs μs μs μs	(9) (9) (9) (9)
175	Package Resonance Frequency	f _{Package}	100	_	_	kHz	(9)

2.8 Dynamic Electrical Characteristics - Supply and SPI

 $V_L \le (V_{CC} - V_{SS}) \le V_H, T_L \le T_A \le T_H, \Delta T \le 25$ K/min, unless otherwise specified

#	Characteristic	Symbol	Min	Тур	Max	Units	
176	Quiescent Current Settling Time (Power Applied to Iq = I _{IDLE} ± 2mA)	t _{SET}		_	5	ms	(3)
177	Reset Recovery Internal Delay (After internal POR)	t _{INT_INIT}	_	16000 / f _{OSC}	_	s	(7)
178 179 180	$\begin{array}{l} V_{CC} \ \text{Micro-cut} \ (C_{BUF} = C_{REG} = C_{REGA} = 1 \ \mu\text{F}) \\ \text{Survival Time} \ (V_{CC} \ \text{disconnect without Reset, } C_{BUF} = C_{REG} = C_{REGA} = 700 \ \text{nF}) \\ \text{Survival Time} \ (V_{CC} \ \text{disconnect without Reset, } C_{BUF} = C_{REG} = C_{REGA} = 1 \ \mu\text{F}) \\ \text{Reset Time} \ (V_{CC} \ \text{disconnect above which Reset is guaranteed}) \end{array}$	tvcc_microcutmin tvcc_microcut tvcc_reset	30 50	_ _ _	<u> </u>	μs μs μs	(3) (3) (3)
181 182 183 184	V _{BUF} , Capacitor Monitor Disconnect Time (Figure 10) POR to first Capacitor Test Disconnect Disconnect Time (Figure 10) Disconnect Delay, Asynchronous Mode (Figure 10) Disconnect Delay, Synchronous Mode (Figure 11)	tPOR_CAPTEST tCAPTEST_TIME tCAPTEST_ADLY tCAPTEST_SDLY		12000 / f _{OSC} 6 / f _{OSC} 688 / f _{OSC} 72 / f _{OSC}		\$ \$ \$ \$	(7) (7) (7) (7)
185 186 187	V _{REG} , V _{REGA} Capacitor Monitor POR to first Capacitor Test Disconnect Disconnect Time Disconnect Rate	tPOR_CAPTEST tCAPTEST_TIME tCAPTEST_RATE		12000 / f _{OSC} 6 / f _{OSC} 256 / f _{OSC}		s s s	(7) (7) (7)
188 189 190 191 192 193 194 195 196 197 198 199 200 201	Serial Interface Timing (See Figure 7, $C_{DOUT} \le 80$ pF, $R_{DOUT} \ge 10$ k Ω) Clock (SCLK) period (10% of V_{CC} to 10% of V_{CC}) Clock (SCLK) high time (90% of V_{CC} to 90% of V_{CC}) Clock (SCLK) low time (10% of V_{CC} to 10% of V_{CC}) Clock (SCLK) rise time (10% of V_{CC} to 10% of V_{CC}) Clock (SCLK) fall time (90% of V_{CC} to 10% of V_{CC}) Clock (SCLK) fall time (90% of V_{CC} to 10% of V_{CC}) \overline{CS} asserted to SCLK high (\overline{CS} = 10% of V_{CC} to SCLK = 10% of V_{CC}) Data setup time (D_{IN} = 10/90% of V_{CC} to SCLK = 10% of V_{CC}) Data hold time (SCLK = 90% of V_{CC} to D_{IN} = 10/90% of V_{CC}) DOUT Data hold time (SCLK = 90% of V_{CC} to D_{IN} = 10/90% of V_{CC}) SCLK low to data valid (SCLK = 10% of V_{CC} to D_{OUT} = 10/90% of V_{CC}) SCLK low to \overline{CS} high (SCLK = 10% of V_{CC} to \overline{CS} = 90% of V_{CC}) \overline{CS} high to \overline{D}_{OUT} disable (\overline{CS} = 90% of V_{CC} to \overline{D}_{OUT} = Hi Z) \overline{CS} high to \overline{CS} low (\overline{CS} = 90% of V_{CC}) to \overline{CS} = 90% of V_{CC})	tsclk tsclkh tsclkk tsclkr tsclkr tsclkr tlead taccess tsetup thold_in thold_out tvalid tlag tdssble tcsn	320 120 120 120 —————————————————————————			ns n	(9) (9) (9) (9) (9) (9) (9) (9) (9) (9)

- 1. Parameters tested 100% at final test.
- 2. Parameters tested 100% at wafer probe.
- 3. Verified by characterization
- 4. * Indicates critical characteristic.
- 5. Verified by qualification testing.
- 6. Parameters verified by pass/fail testing in production.
- 7. Functionality guaranteed by modeling, simulation and/or design verification. Circuit integrity assured through IDDQ and scan testing. Timing is determined by internal system clock frequency.
- 8 N/A
- 9. Verified by simulation.
- 10. N/A.
- 11. Measured at V_{CC} pin; V_{SYNC} guaranteed across full V_{IDLE} range.
- 12. Self-Test repeats on failure up to a ST_RPT_{MAX} times before transmitting Sensor Error Message.
- 13. N/A.
- 14. Thermal resistance between the die junction and the exposed pad; cold plate is attached to the exposed pad.
- 15. Filter cutoff frequencies are directly dependent upon the internal oscillator frequency.

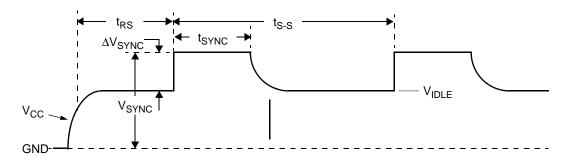


Figure 5. Sync Pulse Characteristics

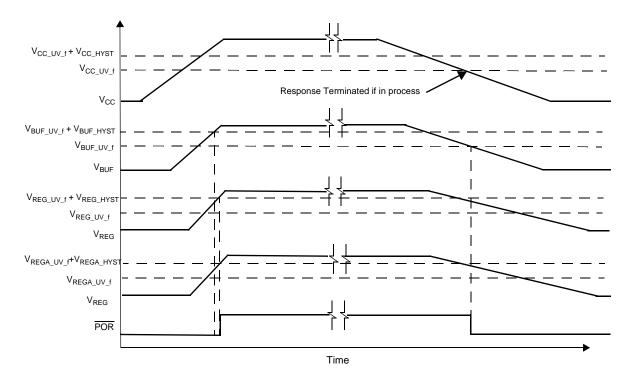


Figure 6. Powerup Timing

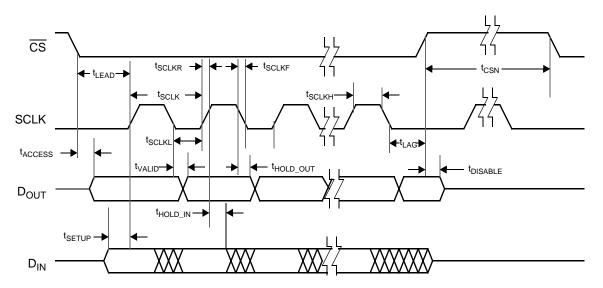


Figure 7. Serial Interface Timing

3 Functional Description

3.1 User Accessible Data Array

A user accessible data array allows for each device to be customized. The array consists of an OTP factory programmable block, an OTP user programmable block, and read only registers for device status. The OTP blocks incorporate independent CRC circuitry for fault detection (reference Section 3.2). Portions of the factory programmable array are reserved for factory-programmed trim values. The user accessible data is shown in Table 2.

Table 2. User Accessible Data

Byte Addr		Nibble Addr		Bit Fu	nction		Nibble Addr		Bit Fu	nction		
(XLong Msg)	Register	(Long Msg)	7	6	5	4	(Long Msg)	3	2	1	0	Туре
\$00	SN0	\$01	SN[7]	SN[6]	SN[5]	SN[4]	\$00	SN[3]	SN[2]	SN[1]	SN[0]	
\$01	SN1	\$03	SN[15]	SN[14]	SN[13]	SN[12]	\$02	SN[11]	SN[10]	SN[9]	SN[8]	
\$02	SN2	\$05	SN[23]	SN[22]	SN[21]	SN[20]	\$04	SN[19]	SN[18]	SN[17]	SN[16]	F, R
\$03	SN3	\$07	SN[31]	SN[30]	SN[29]	SN[28]	\$06	SN[27]	SN[26]	SN[25]	SN[24]	
\$04	DEVCFG1	\$09	0	0	1	0	\$08	0	RNG[2]	RNG[1]	RNG[0]	
\$05	DEVCFG2	\$0B	LOCK_U	PCM	SYNC_PD	LATENCY	\$0A	DATASIZE	BLANKTIME	P_CRC	BAUD	
\$06	DEVCFG3	\$0D	TRANS_MD[1]	TRANS_MD[0]	LPF[1]	LPF[0]	\$0C	TIMESLOTB[9]	TIMESLOTB[8]	TIMESLOTA[9]	TIMESLOTA[8]	
\$07	DEVCFG4	\$0F	TIMESLOTA[7]	TIMESLOTA[6]	TIMESLOTA[5]	TIMESLOTA[4]	\$0E	TIMESLOTA[3]	TIMESLOTA[2]	TIMESLOTA[1]	TIMESLOTA[0]	
\$08	DEVCFG5	\$11	TIMESLOTB[7]	TIMESLOTB[6]	TIMESLOTB[5]	TIMESLOTB[4]	\$10	TIMESLOTB[3]	TIMESLOTB[2]	TIMESLOTB[1]	TIMESLOTB[0]	U, R
\$09	DEVCFG6	\$13	INIT2_EXT	ASYNC	U_DIR[1]	U_DIR[0]	\$12	U_REV[3]	U_REV[2]	U_REV[1]	U_REV[0]	
\$0A	DEVCFG7	\$15	MONTH[3]	MONTH[2]	MONTH[1]	MONTH[0]	\$14	YEAR[3]	YEAR[2]	YEAR[1]	YEAR[0]	
\$0B	DEVCFG8	\$17	CRC_U[2]	CRC_U[1]	CRC_U[0]	DAY[4]	\$16	DAY[3]	DAY[2]	DAY[1]	DAY[0]	
\$0C	SC	\$19	0	TM_B	RESERVED	IDEN_B	\$18	OC_INIT_B	IDEF_B	OFF_B	TEMPF_B	R

Type codes

3.1.1 Device Serial Number Registers

A unique serial number is programmed into the serial number registers of each device during manufacturing. The serial number is composed of the following information:

Bit Range	Content
SN[12:0]	Serial Number
SN[31:13]	Lot Number

Serial numbers begin at 1 for all produced devices in each lot and are sequentially assigned. Lot numbers begin at 1 and are sequentially assigned. No lot will contain more devices than can be uniquely identified by the 13-bit serial number. Depending on lot size and quantities, all possible lot numbers and serial numbers may not be assigned.

The serial number registers are included in the factory programmed OTP CRC verification. Reference Section 3.2.1 for details regarding the CRC verification. Beyond this, the contents of the serial number registers have no impact on device operation or performance, and are only used for traceability purposes.

F: Freescale programmed OTP location

U: User programmable OTP location via PSI5

R: Readable register via PSI5

3.1.2 Factory Configuration Register (DEVCFG1)

The factory configuration register is a factory programmed, read only register which contains user specific device configuration information. The factory configuration register is included in the factory programmed OTP CRC verification.

Loca	ation		Bit						
Address	Register	7	6	5	4	3	2	1	0
\$04	DEVCFG1	0	0	1	0	0	RNG[2]	RNG[1]	RNG[0]
Factory Default		0	0	1	0	0	0	0	0

3.1.2.1 Range Indication Bits (RNG[2:0])

The range indication bits are factory programmed and indicate the full-scale range of the device as shown below.

RNG[2]	RNG[1]	RNG[0]	Full-Scale Acceleration Range	g-Cell Design	PSI5 Init Data Transmission (D9) Reference Table 12
0	0	0	Reserved	N/A	0001
0	0	1	±60g	Medium-g	0111
0	1	0	Reserved	N/A	0010
0	1	1	±120 g	Medium-g	1000
1	0	0	Reserved	N/A	0011
1	0	1	±240 g	High-g	1001
1	1	0	Reserved	N/A	0100
1	1	1	±480 g	High-g	1010

3.1.3 Device Configuration 2 Register (DEVCFG2)

Device configuration register 2 is a user programmable OTP register that contains device configuration information.

Loca	ation	Bit							
Address	Register	7	6	5	4	3	2	1	0
\$05	DEVCFG2	LOCK_U	PCM	SYNC_PD	LATENCY	DATASIZE	BLANKTIME	P_CRC	BAUD
Factory	Default	0	0	0	0	0	0	0	0

3.1.3.1 User Configuration Lock Bit (LOCK_U)

The LOCK U bit allows the user to prevent writes to the user configuration array once programming is completed.

If the LOCK_U bit is written to '1' when a PSI5 "Execute Programming of NVM" command is executed, the LOCK_U OTP bit will be programmed. Upon completion of the OTP programming, an OTP readout will be executed, locking the array from future OTP writes. The User Programmable OTP Array CRC Verification is also activated (Reference Section 3.2.2).

3.1.3.2 PCM Enable Bit (PCM)

The PCM bit enables the PCM output pin. When the PCM bit is set, the PCM output pin is active and outputs a Pulse Code Modulated signal proportional to the acceleration response. Reference Section 3.5.3.7 for more information regarding the PCM output. When the PCM bit is cleared, the PCM output pin is actively pulled low.

PCM	PCM Output
0	Actively Pulled Low
1	PCM Signal Enabled

3.1.3.3 Sync Pulse Pulldown Enable Bit (SYNC_PD)

The sync pulse pulldown enable bit selects if the sync pulse pulldown is enabled once a sync pulse is detected. Reference Section 4.2.1.2 for more information regarding the sync pulse pulldown.

SYNC_PD	Sync Pulse Pulldown
0	Disabled
1	Enabled

If Daisy Chain Mode is enabled, the Sync Pulse Pulldown is enabled as listed below:

SYNC_PD	Daisy Chain Address Programmed	"Run Mode" Command Received	Daisy Chain Address = '001'	Sync Pulse Pulldown
0	х	х	х	Disabled
1	No	Х	Х	Enabled
1	Yes	No	Х	Disabled
1	Yes	Yes	No	Disabled
1	Yes	Yes	Yes	Enabled

3.1.3.4 Latency Selection Bit (LATENCY)

The latency selection bit selects between one of two data latency methods to accommodate synchronized sampling or simultaneous sampling. Reference Section 4.5 for more information regarding latency and data synchronization.

Latency	Data Latency
0	Simultaneous Sampling Mode (Latency relative to Sync Pulse)
1	Synchronous Sampling Mode (Latency relative to Time Slot)

3.1.3.5 Data Size Selection Bit (DATASIZE)

The data size selection bit selects one of two data lengths for the PSI5 response message as shown below.

DATASIZE	Data Length
0	10 Bits
1	8 Bits

3.1.3.6 PSI5 Sync Pulse Blanking Time Selection Bit (BLANKTIME)

The PSI5 sync pulse blanking time selection bit selects the timing for ignoring sync pulses after successful reception of a sync pulse. Reference Section 4.2.1.1 for details regarding sync pulse detection and blanking.

BLANKTIME	Blanking Time Method
0	Maximum of t _{SYNC_OFF_500} or Response Transmission Complete
1	Blanking Time determined by end of response transmission for programmed time slot

3.1.3.7 PSI5 Response Message Error Detection Selection Bit (P_CRC)

The PSI5 response message error detection selection bit selects either even parity, or a 3-Bit CRC for error detection of the PSI5 response message. Reference Section 4.3.3 for details regarding response message error detection.

P_CRC	Parity or CRC
0	Parity
1	CRC

Note: The PSI5 specification recommends parity for data lengths of 10 bits or less.

3.1.3.8 Baud Rate Selection Bit (BAUD)

The baud rate selection bit selects one of two PSI5 baud rates as shown below. Reference Section 2.6 for baud rate timing specifications.

BAUD	Baud Rate
0	Low Baud Rate (125 kBaud)
1	High Baud Rate (190.5 kBaud)

3.1.4 Device Configuration Registers (DEVCFG3, DEVCFG4, DEVCFG5)

Device configuration registers 3, 4, and 5 are user programmable OTP registers which contain device configuration information.

Loc	cation	Bit							
Address	Register	7	6	5	4	3	2	1	0
\$06	DEVCFG3	TRANS_MD[1]	TRANS_MD[0]	LPF[1]	LPF[0]	TIMESLOTB[9]	TIMESLOTB[8]	TIMESLOTA[9]	TIMESLOTA[8]
\$07	DEVCFG4	TIMESLOTA[7]	TIMESLOTA[6]	TIMESLOTA[5]	TIMESLOTA[4]	TIMESLOTA[3]	TIMESLOTA[2]	TIMESLOTA[1]	TIMESLOTA[0]
\$08	DEVCFG5	TIMESLOTB[7]	TIMESLOTB[6]	TIMESLOTB[5]	TIMESLOTB[4]	TIMESLOTB[3]	TIMESLOTB[2]	TIMESLOTB[1]	TIMESLOTB[0]
Factor	y Default	0	0	0	0	0	0	0	0

3.1.4.1 PSI5 Transmission Mode Selection Bits (TRANS_MD[1:0])

The PSI5 transmission mode selection bits select the PSI5 transmission mode as shown below.

TRANS_MD[1]	TRANS_MD[0]	Operating Mode	Reference
0	0	Normal Mode (Asynchronous or Parallel, Synchronous)	Section 4.5.1
0	1	Synchronous Double Sample Rate Mode	Section 4.5.1.3
1	0	16-bit Resolution Mode (2 10-bit Responses)	Section 4.5.2
1	1	Daisy Chain Mode	Section 4.5.4

3.1.4.2 Low-Pass Filter Selection Bit (LPF[1:0])

The low-pass filter selection bits select the low-pass filter for the acceleration signal as described below:

LPF[1]	LPF[0]	Low-Pass Filter Selected
0	0	400 Hz, 3-Pole
0	1	400 Hz, 4-Pole
1	0	Reserved
1	1	Reserved

3.1.4.3 TimeSlot Selection Bits (TIMESLOTx[9:0])

The timeslot selection bits select the time slot(s) to be used for data transmission. Reference Section 4.5 for details regarding PSI5 transmission modes and time slots. Accepted time slot values are $0.5 \mu s$ to $511.5 \mu s$ in $0.5 \mu s$ increments. Care must be taken to prevent from programming time slots which violate the PSI5 Version 1.3 specification, or time slots which will cause data contention.

TIMESLOTx[9:0]	ASYNC Bit	Time Slot	Reference
00 0000 0000	0	Default Time Slot (t _{TIMESLOT_DFLT}) from start of Sync Pulse (t _{TRIG})	Section 4.5
00 0000 0000	1	Asynchronous Mode	Section 4.5.1.1
Non-Zero	N/A	TimeSlot Definition from start of Sync Pulse (t _{TRIG}) in 0.5μs Increments	Section 4.5

Note: TIMESLOTB is only used for Synchronous Double Sample Rate Mode and 16-Bit Resolution Mode.

MMA52xxKW

3.1.5 Device Configuration Registers 6, 7, and 8 (DEVCFG6, DEVCFG7, DEVCFG8)

Device configuration registers 6, 7 and 8 are user programmable OTP registers which contain device configuration and user specific manufacturing information. The user specific manufacturing information bits have no impact on the performance, but are transmitted during the PSI5 initialization phase 2 in 10-bit mode.

Location		Bit							
Address	Register	7	6	5	4	3	2	1	0
\$09	DEVCFG6	INIT2_EXT	ASYNC	U_DIR[1]	U_DIR[0]	U_REV[3]	U_REV[2]	U_REV[1]	U_REV[0]
\$0A	DEVCFG7	MONTH[3]	MONTH[2]	MONTH[1]	MONTH[0]	YEAR[3]	YEAR[2]	YEAR[1]	YEAR[0]
\$0B	DEVCFG8	CRC_U[2]	CRC_U[1]	CRC_U[0]	DAY[4]	DAY[3]	DAY[2]	DAY[1]	DAY[0]
Factory	Default	0	0	0	0	0	0	0	0

3.1.5.1 Initialization Phase 2 Data Extension Bit (INIT2_EXT)

The initialization phase 2 data extension bit enables or disables data transmission in data fields D27 through D32 of PSI5 Initialization Phase 2 as shown below.

INIT2_EXT	Description
0	D27 through D32 are set to "0000"
1	D27 through D32 are transmitted as defined in Section 4.4.2.1

3.1.5.2 Asynchronous Mode Bit (ASYNC)

The asynchronous mode bit enables asynchronous data transmission as described in Section 3.1.4.3.

3.1.5.3 User Sensing Direction (U_DIR[1:0])

The user sensing direction registers are user programmable OTP registers which contain the module level sensing direction. This data is transmitted to the main ECU during PSI5 initialization phase 2 in 10-bit mode, as described in Section 4.4.2.1.

U_DIR[1]	U_DIR[0]	Module Sensing Direction As Defined in AKLV27	PSI5 Init Data Transmission (D8) Reference Table 12
0	0	Connector Direction (β)	0000
0	1	Bushing Direction (α)	0100
1	0	Perpendicular to α and β (γ)	1000
1	1	Not used	1100

3.1.5.4 User Product Revision (U REV[3:0])

The user product revision registers are user programmable OTP registers which contain the module production revision. The device supports up to 16 product revisions. This data is transmitted to the main ECU during PSI5 initialization phase 2 in 10-bit mode, as described in Section 4.4.2.1.

3.1.5.5 User Production Date Information (YEAR[3:0], MONTH[3:0], DAY[4:0)

The user production date information registers are user programmable OTP registers which contain the module production date. The table below shows the relationship between the stored values and the production date.

Programmed Value	Decoded Value	Julian Date Value
YEAR[3:0]	Year	JY[6:0]
0000	2009	0001001
•	•	•
•	•	•
<u> </u>	•	•
1111	2024	0011000
MONTH[3:0]	Month	JM[3:0]
0000	N/A	0000
0001	January	0001
•	•	•
•	•	•
•	•	•
1100	December	1100
•	•	•
•	•	•
•	•	•
1111	N/A	N/A
DAY[4:0]	Day	JD[4:0]
00000	N/A	00000
00001	Day 1	00001
•	•	•
•	•	•
•	•	•
11111	Day 31	11111

The Julian date value is transmitted to the main ECU during PSI5 initialization phase 2 in 10-bit mode, as described in Section 4.4.2.2.

3.1.5.6 User Configuration CRC (CRC_U[2:0])

The user configuration CRC bits contain the 3-bit CRC used for verification of the user programmable OTP array. Reference Section 3.2.2 for information regarding the CRC for the user programmable OTP array.

3.1.6 Status Check Register (SC)

The status check register is a read-only register containing device status information.

Location					В	Bit			
Address	Register	7	6	5	4	3	2	1	0
\$0C	SC	0	TM_B	RESERVED	IDEN_B	OC_INIT_B	IDEF_B	OFF_B	TEMPF_B

3.1.6.1 Test Mode Flag (TM_B)

The test mode bit is cleared if the device is in test mode.

TM_B	Operating Mode
0	Test Mode is active
1	Test Mode is not active

3.1.6.2 Internal Data Error Flag (IDEN_B)

The internal data error bit is cleared if a register data CRC fault is detected in the user accessible OTP array. A device reset is required to clear the error.

IDEN_B	Error Condition
0	CRC error in user programmable OTP array
1	No error detected

3.1.6.3 Offset Cancellation Init Status Flag (OC_INIT_B)

The offset cancellation initialization status bit is set once the offset cancellation initialization process is complete, and the filter has switched to normal mode.

OC_INIT_B	Error Condition
0	Offset Cancellation in initialization
1	Offset Cancellation initialization complete (t _{OC1} and t _{OC2} expired)

3.1.6.4 Internal Factory Data Error Flag (IDEF_B)

The internal factory data error bit is cleared if a register data CRC fault is detected in the factory programmable OTP array. A device reset is required to clear the error.

IDEF_B	Error Condition
0	CRC error in factory programmable OTP array
1	No error detected

3.1.6.5 Offset Error Flag (OFF_B)

The offset error flag is cleared if the acceleration signal reaches the offset limit.

OFF_B	Error Condition
0	Offset error detected
1	No error detected

3.1.6.6 Temperature Error Flag (TEMPF_B)

The temperature error flag is cleared if an over or under temperature condition exists.

TEMPF_B	Error Condition
0	Over- or Under-Temperature error condition detected
1	No error detected

3.2 OTP Array CRC Verification

3.2.1 Factory Programmed OTP Array CRC Verification

The Factory programmed OTP array is verified for errors with a 3-bit CRC. The CRC verification is enabled only when the factory programmed array is locked. The CRC verification uses a generator polynomial of $g(x) = X^3 + X + 1$, with a seed value = '111'.

Once the CRC verification is enabled, the CRC is continuously calculated on all bits in registers \$00, \$01, \$02, \$03, and \$04 and on the factory programmable device configuration bits with the exception of the factory lock bit. Bits are fed in from right to left (LSB first), and top to bottom (lower addresses first) in the register map. The calculated CRC is then compared against the stored 3 bit CRC. If a CRC error is detected in the OTP array, the IDEF_B bit is cleared in the SC register.

The CRC verification is completed on the memory registers which hold a copy of the fuse array values, not the fuse array values.

3.2.2 User Programmable OTP Array CRC Verification

The user programmable OTP array is independently verified for errors with a 3-bit CRC. The CRC verification is enabled only when the LOCK_U bit in the user data register array is set after POR, or after a PSI5 Programming Mode "Execute Programming of NVM" command. The CRC verification uses a generator polynomial of $g(x) = X^3 + X + 1$, with a seed value = '111'. The calculated CRC is compared against a user programmable 3-bit CRC, CRC_U[2:0], which is also included in the user programmable array.

Once the CRC verification is enabled, the CRC is continuously calculated on all bits in registers \$05, \$06, \$07, \$08, \$09, \$0A, and \$0B with the exception of the LOCK_U bit and the CRC_U[2:0] bits. Bits are fed in from right to left (LSB first), and top to bottom (lower addresses first) in the register map. The calculated CRC is then compared against the CRC_U[2:0] bits. If a CRC mismatch is detected, the IDEN_B bit is cleared in the SC register.

The CRC verification is completed on the memory registers which hold a copy of the fuse array values, not the fuse array values.

3.3 Voltage Regulators

The device derives its internal supply voltage from the V_{CC} and V_{SS} pins. Separate internal voltage regulators are used for the analog (V_{REGA}) and digital circuitry (V_{REG}). The analog and digital regulators are supplied by a buffer regulator (V_{BUF}) to provide immunity from EMC and supply dropouts on V_{CC} . External filter capacitors are required, as shown in Figure 1.

The voltage regulator module includes voltage monitoring circuitry which holds the device in reset following power-on until the internal voltages have increased above the undervoltage detection thresholds. The voltage monitor asserts internal reset when the external supply or internally regulated voltages fall below the undervoltage detection thresholds. A reference generator provides a reference voltage for the $\Sigma\Delta$ converter.

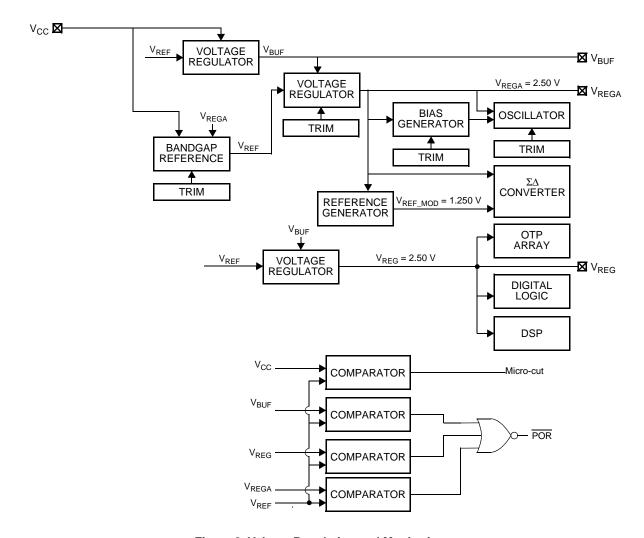


Figure 8. Voltage Regulation and Monitoring

3.3.1 V_{BUF}, V_{REG}, and V_{REGA} Regulator Capacitor

The internal regulators require an external capacitor between each of the regulator pins (V_{BUF} , V_{REG} , or V_{REGA}) and the associated the V_{SS} / V_{SSA} pin for stability. Figure 1 shows the recommended types and values for each of these capacitors.

3.3.2 V_{CC}, V_{BUF}, V_{REG}, and V_{REGA} Undervoltage Monitor

A circuit is incorporated to monitor the supply voltage (V_{CC}) and all internally regulated voltages (V_{BUF} , V_{REG} and V_{REGA}). If any of internal regulator voltages fall below the specified undervoltage thresholds in Section 2, the device will be reset. If V_{CC} falls below the specified threshold, PSI5 transmissions are terminated for the present response. Once the supply returns above the threshold, the device will respond to the next detected sync pulse. Reference Figure 9.

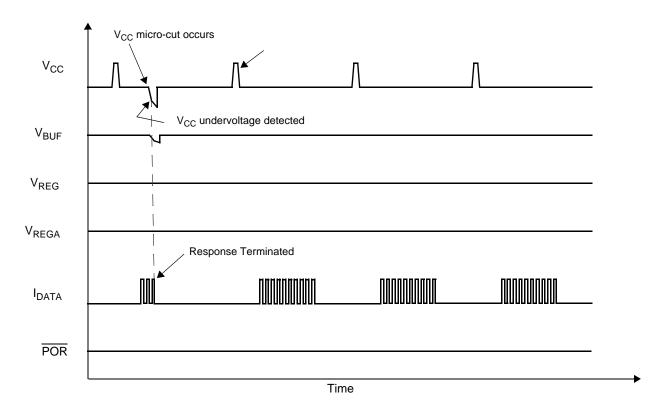


Figure 9. V_{CC} Micro-Cut Response

3.3.3 V_{BUF}, V_{REG}, and V_{REGA} Capacitance Monitor

A monitor circuit is incorporated to ensure predictable operation if the connection to the external V_{BUF} , V_{REG} , or V_{REGA} , capacitor becomes open.

In asynchronous mode, the V_{BUF} regulator is disabled $t_{CAPTEST_ADLY}$ seconds after each data transmission for a duration of $t_{CAPTEST_TIME}$ seconds. If the external capacitor is not present, the regulator voltage will fall below the internal reset threshold, forcing a device reset.

In synchronous mode, the V_{BUF} regulator is disabled $t_{CAPTEST_SDLY}$ seconds after each sync pulse for a duration of $t_{CAPTEST_TIME}$ seconds. If the external capacitor is not present, the regulator voltage will fall below the internal reset threshold, forcing a device reset.

The V_{REG} and V_{REGA} regulators are disabled at a continuous rate ($t_{CAPTEST_RATE}$), for a duration of $t_{CAPTEST_TIME}$ seconds. If either external capacitor is not present, the associated regulator voltage will fall below the internal reset threshold, forcing a device reset.

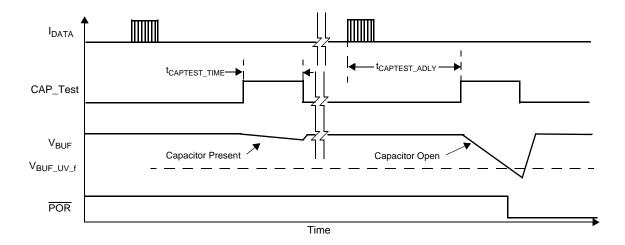


Figure 10. V_{BUF} Capacitor Monitor - Asynchronous Mode

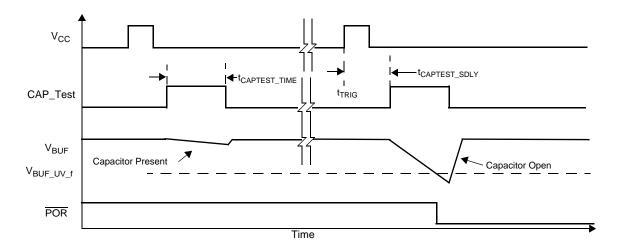


Figure 11. V_{BUF} Capacitor Monitor - Synchronous Mode

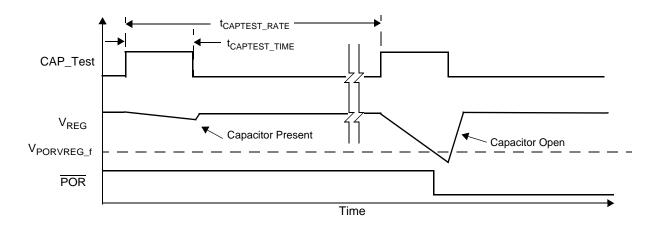


Figure 12. V_{REG} Capacitor Monitor

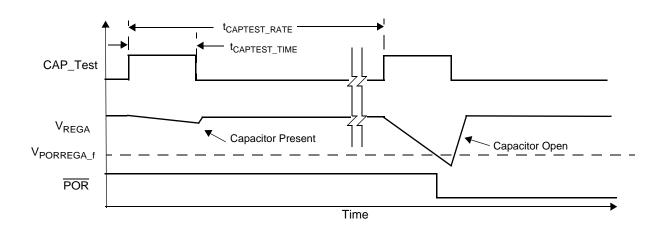


Figure 13. V_{REGA} Capacitor Monitor

3.4 Internal Oscillator

A factory trimmed oscillator is included as specified in Section 2.

3.5 Acceleration Signal Path

3.5.1 Transducer

The transducer is an overdamped mass-spring-damper system defined by the following transfer function: where:

$$H(s) = \frac{\omega_n^2}{s^2 + 2 \cdot \xi \cdot \omega_n \cdot s + \omega_n^2}$$

 ζ = Damping Ratio

 ω_n = Natural Frequency = 2 * Π * f_n

Reference Section 2.7 for transducer parameters.

3.5.2 $\Sigma\Delta$ Converter

A sigma delta modulator converts the differential capacitance of the transducer to a 1 MHz data stream that is input to the DSP block.

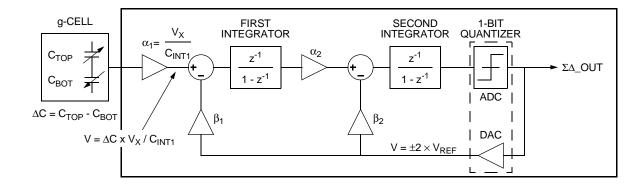


Figure 14. $\Sigma\Delta$ Converter Block Diagram

3.5.3 Digital Signal Processing Block

A Digital Signal Processing (DSP) block is used to perform signal filtering and compensation. A diagram illustrating the signal processing flow within the DSP block is shown in Figure 15.

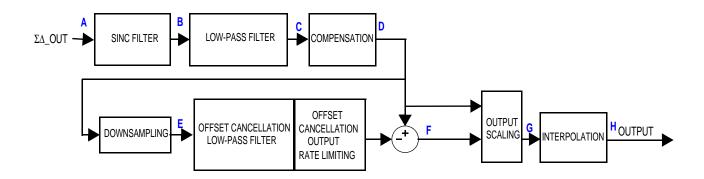


Figure 15. Signal Chain Diagram

Table 3. Signal Chain Characteristics

	Description	Sample Time (µs)	Data Width (Bits)	Over Range (Bits	Signal Width (Bits)	Signal Noise (Bits)	Signal Margin (Bits)	Typical Block Latency	Reference
A	SD	1	1		1			203/f _{osc}	Section 3.5.2
В	SINC Filter	16	20		13			200/1 _{0SC}	Section 3.5.3.2
С	Low-Pass Filter	16	26	4	10	3	9	Reference Section 3.5.3.2	Section 3.5.3.2
D	Compensation	16	26	4	10	3	9	68/f _{osc}	
E	Down Sampling	16	26	4	10	3	9	00/1 _{0SC}	
F	High Pass Filter	16	26	4	10	3	9	Reference Section 3.5.3.3	Section 3.5.3.3
G	DSP Sampling	16			10			4/f _{osc}	Section 3.5.3.5
3	10-Bit Output Scaling	1 '0			10			T/10SC	000tion 3.3.3.3
Н	Interpolation	1			10			64/f _{osc}	Section 3.5.3.5

3.5.3.1 Decimation Sinc Filter

The serial data stream produced by the $\Sigma\Delta$ converter is decimated and converted to parallel values by a 3rd order 16:1 sinc filter with a decimation factor of 16.

$$H(z) = \left[\frac{1 - z^{-16}}{16 \times (1 - z^{-1})}\right]^3$$

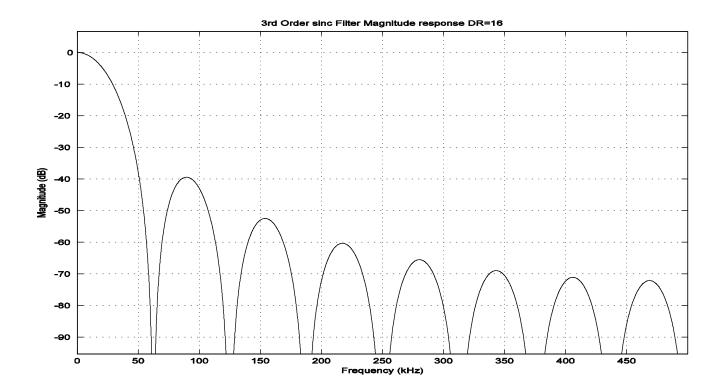


Figure 16. Sinc Filter Response, t_S = 16 μs

3.5.3.2 Low-Pass Filter

Data from the Sinc filter is processed by an infinite impulse response (IIR) low-pass filter.

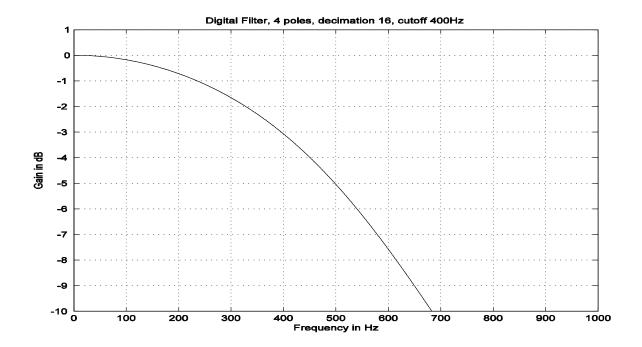
$$\mathsf{H}(z) \, = \, a_0 \, \cdot \, \frac{(\mathsf{n}_{11} \cdot \mathsf{z}^0) + (\mathsf{n}_{12} \cdot \mathsf{z}^{-1}) + (\mathsf{n}_{13} \cdot \mathsf{z}^{-2})}{(\mathsf{d}_{11} \cdot \mathsf{z}^0) + (\mathsf{d}_{12} \cdot \mathsf{z}^{-1}) + (\mathsf{d}_{13} \cdot \mathsf{z}^{-2})} \cdot \frac{(\mathsf{n}_{21} \cdot \mathsf{z}^0) + (\mathsf{n}_{22} \cdot \mathsf{z}^{-1}) + (\mathsf{n}_{23} \cdot \mathsf{z}^{-2})}{(\mathsf{d}_{11} \cdot \mathsf{z}^0) + (\mathsf{d}_{22} \cdot \mathsf{z}^{-1}) + (\mathsf{d}_{23} \cdot \mathsf{z}^{-2})}$$

The device provides the option for one of two low-pass filters. The filter is selected with the LPF[1:0] bits in the DEVCFG3 register. The filter selection options are listed in Section 3.1.4.2. Response parameters for the low-pass filter are specified in Section 2.7. Filter characteristics are illustrated in Figure 17 and Figure 18.

Table 4. Low-Pass Filter Coefficients

Description		Filter (Group Delay		
	a ₀	5.189235225042199e-02			
	n ₁₁	1.629077582099646e-03	d ₁₁	1.0	
	n ₁₂	1.630351547919014e-03	d ₁₂	-9.481076477495780e-01	
400 Hz, 3-Pole LPF	n ₁₃	0	d ₁₃	0	2816/f _{osc}
	n ₂₁	2.500977520825902e-01	d ₂₁	1.0	
	n ₂₂	4.999999235890745e-01	d ₂₂	-1.915847097557409e+00	
	n ₂₃	2.499023243303036e-01	d ₂₃	9.191065266874253e-01	
	a ₀	3.143225986084408e-03			
	n ₁₁	9.951105668343345e-04	d ₁₁	1.0	
	n ₁₂	2.003487780064749e-03	d ₁₂	-1.892328151433503e+00	
400 Hz, 4-Pole LPF	n ₁₃	1.008466113720278e-03	d ₁₃	8.954713774195870e-01	3392/f _{osc}
	n ₂₁	2.516720624825626e-01	d ₂₁	1.0	
	n ₂₂	4.999888752940916e-01	d ₂₂	-1.918978239761011e+00	
	n ₂₃	2.483390622233452e-01	d ₂₃	9.229853042218408e-01	

Note: Low-Pass Filter values do not include g-cell frequency response.



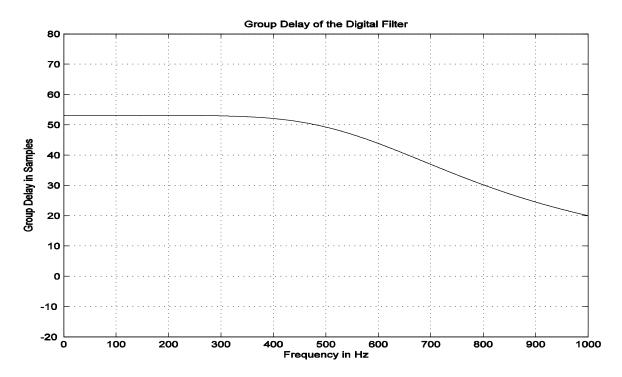
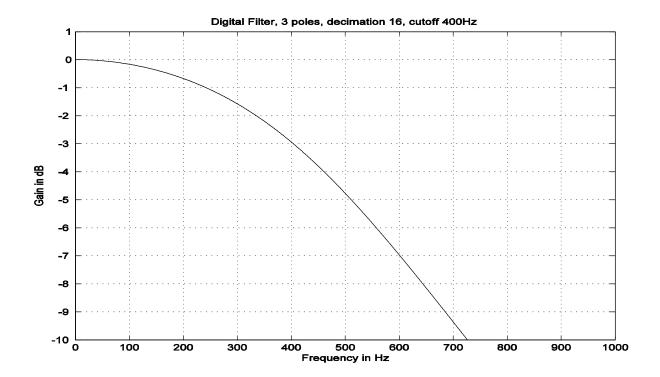


Figure 17. Low-Pass Filter Characteristics: f_{C} = 400 Hz, 4-Pole, t_{S} = 16 μs



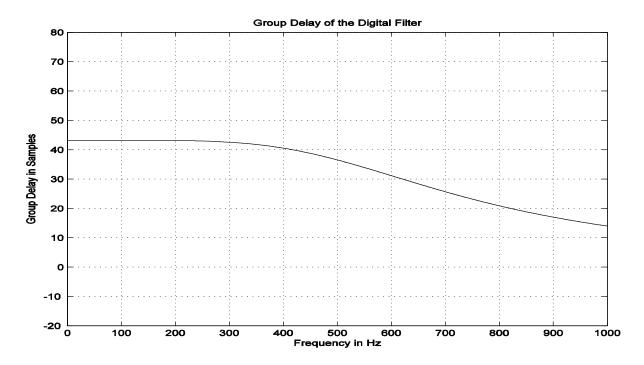


Figure 18. Low-Pass Filter Characteristics: f_{C} = 400 Hz, 3-Pole, t_{S} = 16 μs

3.5.3.3 Offset Cancellation

The device provides an optional offset cancellation circuit to remove internal offset error. A block diagram of the offset cancellation is shown in Figure 19.

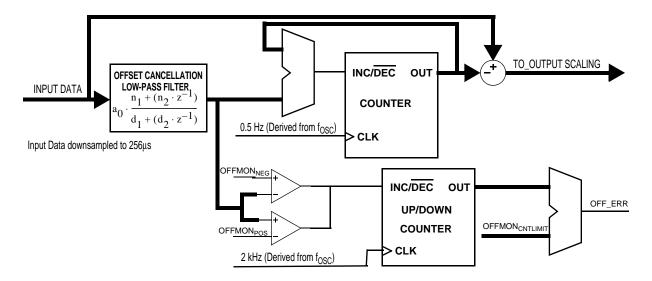


Figure 19. Offset Cancellation Block Diagram

The transfer function for the offset LPF is:

$$H(z) = ao_0 \cdot \frac{no_1 + (no_2 \cdot z^{-1})}{do_1 + (do_2 \cdot z^{-1})}$$

Response parameters are specified in Section 2 and the offset LPF coefficients are specified in Table 6.

During startup, two phases of the offset LPF are used to allow for fast convergence of the internal offset error during initialization. The timing and characteristics of each phase are shown in Table 5 and Table 6 and specified in Section 2. For more information regarding the startup timing, reference the PSI5 initialization information in Section 4.4. The offset low-pass filter used in normal operation is selected by the OC_FILT bit as shown in Table 5.

During the Initialization Self-Test phase, the offset cancellation circuit output value is frozen.

During normal operation, output rate limiting is applied to the output of the high pass filter. Rate limiting updates the offset cancellation output by $OFF_{Step\ xx}$ LSB every $t_{OffRate\ xx}$ seconds.

Table 5. Offset Cancellation Startup Characteristics and Timing

Offset Cancellation Startup Phase	Offset LPF	Output Rate Limiting	Total Time for Phase					
1	10 Hz	Bypassed	80 ms					
2	0.3 Hz	Bypassed	70 ms					
Self-Test	0.3 Hz	Bypassed (Frozen during ST2)	96 ms per Self-Test Sequence (up to 6 repeats)					
Complete	0.1 Hz	Enabled	N/A					

Table 6. High Pass Filter Coefficients

Description		Co	efficients		Group Delay
	ao ₀	0.015956938266754			
10 Hz HPF	no ₁	0.499998132328277	do ₁	1.0	16.384 ms
	no ₂	0.499998132328277	do ₂	-0.984043061733246	
	ao ₀	0.000482380390167			
0.3 Hz HPF	no ₁	0.499938218213271	do ₁	1.0	537.6 ms
	no ₂	0.499938218213271	do ₂	-0.999517619609833	
	ao ₀	0.0001608133316040			
0.1 Hz HPF	no ₁	0.4999999403953552	do ₁	1.0	1591ms
	no ₂	0.4999999403953552	do ₂	-0.9998391270637512	
	ao ₀	0.0000643134117126			
0.04 Hz HPF	no ₁	0.4999999403953552	do ₁	1.0	3976ms
	no ₂	0.4999999403953552	do ₂	-0.9999356269836426	

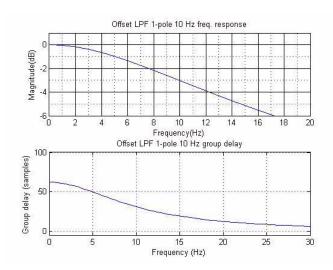


Figure 20. 10Hz Offset Cancellation Low-Pass Filter Characteristics

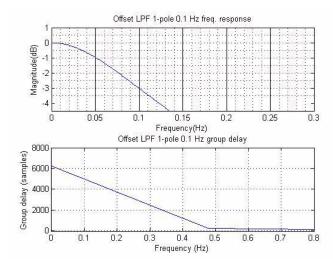


Figure 21. 0.1 Hz Offset Cancellation Low-Pass Filter Characteristics

3.5.3.4 Offset Monitor

The device includes an offset monitor circuit. The output of the single pole low-pass filter in the offset cancellation block is continuously monitored against the offset limits specified in Section 2.4. An up/down counter is employed to count up If the output exceeds the limits, and to count down if the output is within the limits. The output of the counter is compared against the count limit OFFMON_{CNTLIMIT}. If the counter exceeds the limit, the OFF_B flag in the SC register is cleared. The counter rails once the max counter value is reached (OFFMON_{CNTSIZE}). The offset monitor is disabled during Initialization Phase 1, Phase 2, and Phase 3.

3.5.3.5 Data Interpolation

The device includes 16 to 1 linear data interpolation to minimize the system sample jitter. Each result produced by the digital signal processing chain is delayed one sample time. On detection of a sync pulse the transmitted data is interpolated from the 2 previous samples, resulting in a latency of one sample time, and a maximum signal jitter of $\pm 1/16$ of a sample time. Reference Section 4.5 for more information regarding interpolation and data latency.

3.5.3.6 Output Scaling

The 26 bit digital output from the DSP is clipped and scaled to a 10-bit or 8-bit word which spans the acceleration range of the device. Figure 22 shows the method used to establish the output acceleration data word from the 26-bit DSP output.

Over Range Signal										Noise				Margin							
D25	D24	D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	D11	D10	D9	D8		D2	D1	D0
	8-bit Da	ta Word	t	D21	D20	D19	D18	D17	D16	D15	D14	Using Rounding									
,	10-bit Da	ata Wor	d	D21	D20	D19	D18	D17	D16	D15	D14	4 D13 D12 Using Rounding									

Figure 22. 10-Bit Output Scaling Diagram

3.5.3.7 PCM Output Function

The device provides the option for a PCM output function. The PCM output is activated if the PCM bit is set in the DEVCFG2 register. When the PCM function is enabled, a 4 MHz Pulse Code Modulated signal proportional to the upper 9 bits of the 10-bit acceleration response is output onto the PCM pin. The PCM output is intended for test use only.

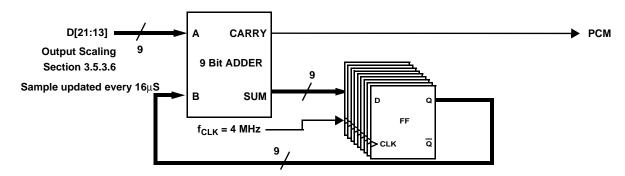


Figure 23. PCM Output Function Block Diagram

3.6 Overload Response

3.6.1 Overload Performance

The device is designed to operate within a specified range. Acceleration beyond that range (overload) impacts the output of the sensor. Acceleration beyond the range of the device can generate a DC shift at the output of the device that is dependent upon the overload frequency and amplitude. The g-cell is overdamped, providing the optimal design for overload performance. However, the performance of the device during an overload condition is affected by many other parameters, including:

- · g-cell damping
- Non-linearity
- · Clipping limits
- Symmetry

Figure 24 shows the g-cell, ADC and output clipping of The device over frequency. The relevant parameters are specified in Section 2.

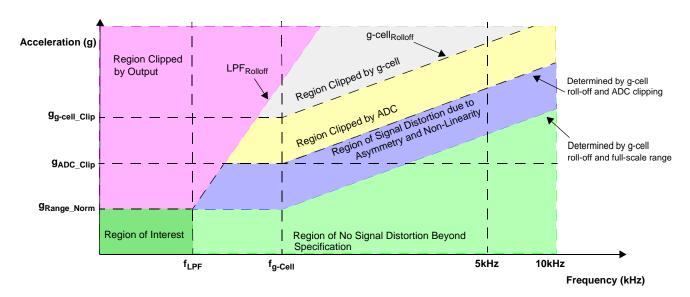


Figure 24. Output Clipping vs. Frequency

3.6.2 Sigma Delta Modulator Over Range Response

Over Range conditions exist when the signal level is beyond the full-scale range of the device but within the computational limits of the DSP. The $\Sigma\Delta$ converter can saturate at levels above those specified in Section 2 (G_{ADC_CLIP}). The DSP operates predictably under all cases of over range, although the signal may include residual high frequency components for some time after returning to the normal range of operation due to non-linear effects of the sensor.

4 PSI5 Layer and Protocol

4.1 Communication Interface Overview

The communication interface between a master device and the MMA52xx is established via a PSI5 compatible 2-wire interface, with parallel or serial (daisy-chain) connections to the satellite modules. Figure 25 shows one possible system configuration for multiple satellite modules in parallel.

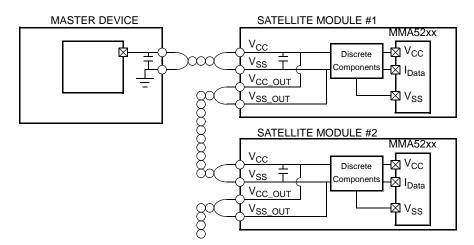


Figure 25. PSI5 Satellite Interface Diagram

4.2 Data Transmission Physical Layer

The device uses a two wire interface for both its power supply (V_{CC}), and data transmission. The PSI5 master supplies a preregulated voltage. Data transmissions and synchronization control from the PSI5 master to the device are accomplished via modulation of the supply voltage. Data transmissions from the device to the PSI5 master are accomplished via modulation of the current on the power supply line.

4.2.1 Synchronization Pulse

The PSI5 master modulates the supply voltage in the positive direction to provide synchronization of the satellite sensor data. Upon reception of a synchronization pulse, the device delays a specified period of time, called a time slot, before transmitting acceleration data. For more details regarding time slots, refer to Section 3.1.4, and Section 4.5.

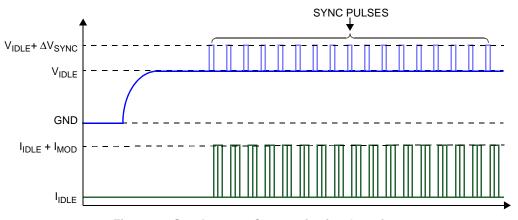


Figure 26. Synchronous Communication Overview

4.2.1.1 Synchronization Pulse Detection

The Synchronization (Sync) pulse detection block generates a valid synchronization pulse signal following the detection of an externally generated Sync pulse. This signal resets the Sync pulse time reference (t_{TRIG}), and initiates the timers associated with response messages.

The supply voltage can vary throughout the specified range, so the external Sync pulses may have different absolute voltage levels. Thus, the Sync pulse detection threshold (V_{CC_SYNC}) is dependent not only on the Sync pulse absolute voltage, but also on the supply voltage. Figure 27 shows a block diagram of the Sync pulse detection circuit.

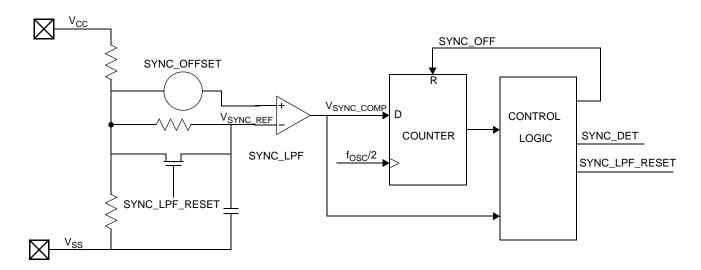


Figure 27. Synchronization Pulse Detection Circuit

The start of a Sync pulse is detected when the comparator output is set (V_{SYNC} exceeds V_{SYNC_REF}). The comparator output is input into a counter, and the counter is updated at a fixed frequency of $f_{OSC}/2$. At a fixed time after the initial sync pulse detection ($t_{SYNC_LPF_RST_ST}$), the counter is compared against a limit (the minimum value of t_{SYNC}). If the counter is above the limit, a valid sync pulse is detected.

If the Sync pulse is valid, the following occur:

- 1. The valid Sync pulse detection signal is set.
- The detection counter is reset and disabled for t_{SYNC_OFF} (referenced from t_{TRIG}). t_{SYNC_OFF} is a user programmable option. Reference Section 3.1.3.6 for details on the selectable option, and Section 2.6 for timing specifications for each option.
 - a. If BLANKTIME = '0', $t_{SYNC_OFF} = t_{SYNC_OFF_500}$
- 3. The Sync pulse detection low-pass filter is reset for a specified time (t_{SYNC_LPF_RESET)}.

If the Sync pulse is invalid, all timers are reset, and the detector becomes sensitive for the very next f_{SYNC DET} sample.

The output of the comparator is monitored at the $f_{OSC}/2$ frequency. Once the comparator output goes high, all of the internal timers are started, so that the t_{TRIG} jitter is minimized.

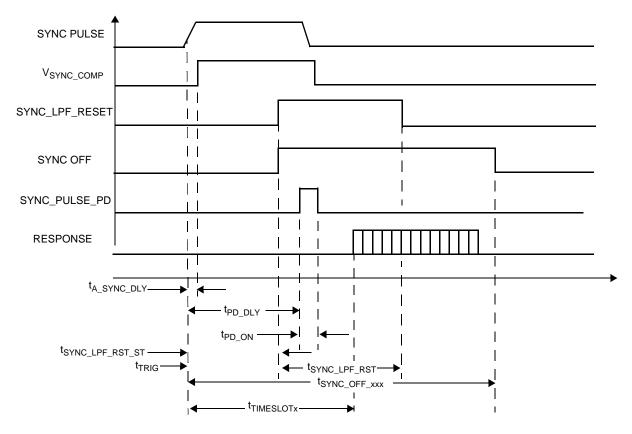


Figure 28. Synchronization Pulse Detection Timing

4.2.1.2 Synchronization Pulse Pulldown Function

The device includes an optional Sync pulse pulldown function for systems in which the master device does not include an active pulldown function. The modulation current pulldown circuit is used, which sinks I_{MOD} - I_{IDLE} additional current from the I_{DATA} pin. The pulldown current is activated after t_{PD-DLY} (referenced to t_{TRIG}), and is activated for t_{PD-ON} .

4.3 Data Transmission Data Link Layer

4.3.1 Bit Encoding

The device outputs data by modulation of the V_{CC} current using Manchester 2 Encoding. Data is stored in a transition occurring in the middle of the bit time. The signal idles at the normal quiescent supply current. A logic low is defined as an increase in current at the middle of a bit time. A logic high is defined as a decrease in current at the middle of a bit time. There is always a transition in the middle of the bit time. If consecutive "1" or "0" data are transmitted, There will also be a transition at the start of a bit time.

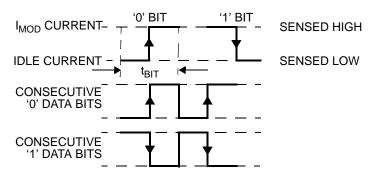


Figure 29. Manchester 2 Data Bit Encoding

MMA52xxKW

4.3.2 Data Transmission

Transmission frames are composed of two start bits, an 8-Bit or 10-bit data word, and error detection bit(s). Data words are transmitted least-significant bit (LSB) first. A typical Manchester-encoded transmission frame is illustrated in Figure 30.

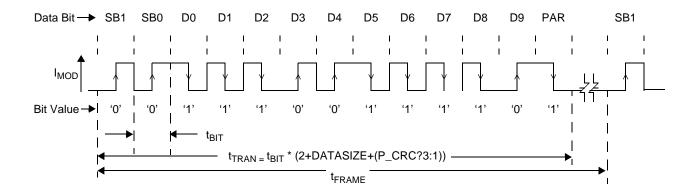


Figure 30. Example Manchester Encoded Data Transfer - PSI5-x10P

4.3.3 Error Detection

Error detection of the transmitted data is accomplished via either a parity bit, or a 3-Bit CRC. The type of error detection used is selected by the P_CRC bit in the DEVCFG register.

4.3.4 Parity Error Detection

When parity error detection is selected, even parity is employed. The number of logic '1' bits in the transmitted message must be an even number.

4.3.5 3-Bit CRC Error Detection

When CRC error detection is selected, a 3-bit CRC is appended to each response message. The 3-bit CRC uses a generator polynomial of $g(x) = X^3 + X + 1$, with a seed value = '111'. Data from the transmitted message is read into the CRC calculator LSB first, and the data is augmented with three '0's. Start bits are not used in the CRC calculation. Table 7 shows some example CRC calculation values for 10-bit data transmissions.

Table 7. PSI5 3-Bit CRC Calculation Examples

	Data Transmitted												CRC		
HEX	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	C2	C1	C0		
0x000	0	0	0	0	0	0	0	0	0	0	1	1	0		
0x0CC	0	0	1	1	0	0	1	1	0	0	0	1	1		
0x151	0	1	0	1	0	1	0	0	0	1	0	0	0		
0x1E0	0	1	1	1	1	0	0	0	0	0	0	1	1		
0x1F4	0	1	1	1	1	1	0	1	0	0	0	1	0		
0x220	1	0	0	0	1	0	0	0	0	0	1	0	0		
0x275	1	0	0	1	1	1	0	1	0	1	1	1	1		
0x333	1	1	0	0	1	1	0	0	1	1	0	0	1		
0x3FF	1	1	1	1	1	1	1	1	1	1	1	0	0		

4.3.6 Data Range Values

Table 9 shows the details for each data range.

Table 8. PSI5 Data Values

8-Bit Dat	ta Value	10-Bit Da	ta Value	Description
Decimal	Hex	Decimal	Hex	Description
		+511	\$1FF	
		•	•	
+127	\$7F	•	•	Reserved
		•	•	-
		+502	\$1F6	
+126	\$7E	+501	\$1F5	
+125	\$7D	+500	\$1F4	Sensor Defect Error Message
		+499	\$1F3	
N/A	N/A	:	•	Decembed
IN/A	IN/A			Reserved
		+489	\$1E9	
+124	\$7C	+488	\$1E8	Sensor Busy
+123	\$7B	+487	\$1E7	Sensor Ready
+122	\$7A	+486	\$1E6	Sensor Ready, but Unlocked
	****	+485	\$1E5	
N 1/A	N//0	•	•	-
N/A	N/A	•	•	Reserved
		•	•	
+121	\$79	+481	\$1E1	
+120	\$78	+480	\$1E0	Maximum positive acceleration value
•	•	•	•	
•			•	
+3	\$03	+3	\$03	Positive acceleration values
+3	\$03	+3	\$03	_
+2	\$02	+2	\$02 \$01	_
0	0	0	0	0g level
-1	\$FF	-1	\$3FF	og level
-1	\$FE	-1	\$3FE	Negative acceleration values
-3	\$FD	-3	\$3FD	inegative acceleration values
-3	\$50	-3	\$3FD	
•	•	•	•	
-120	\$88	-480	\$220	Maximum negative acceleration value
-121	\$87	-481	\$21F	
•	•	•	•	Initialization Data Codes
•	•	•	•	10-Bit Status Data Nibble 1 - 16 (0000 - 1111) (Dx)
•	•	•	0040	8-Bit Status Data Nibble 1 - 4 (00 - 11) (Dx)
-124	\$84	-496	\$210	
-125	\$83	-497	\$20F	
•			•	Initialization Data IDs Block ID 1 - 16 (10-bit Mode) (IDx)
•			•	Block ID 1 - 16 (10-bit Mode) (IDx) Block ID 1 - 4 (8-Bit Mode) (IDx)
-128	\$80	-512	\$200	(
	400		\$200	

4.4 Initialization

Following powerup, the device proceeds through an initialization process which is divided into 3 phases:

- · Initialization Phase 1: No Data transmissions occur
- Initialization Phase 2: Sensor self-test and transmission of configuration information
- Initialization Phase 3: Transmission of "Sensor Busy", and "Sensor Ready" / "Sensor Defect" message

Once initialization is completed the device begins normal mode operation, which continues as long as the supply voltage remains within the specified limits.

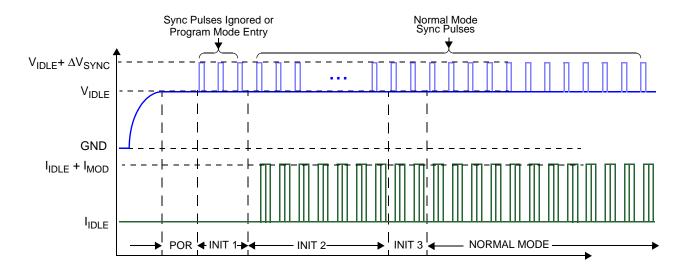


Figure 31. PSI5 Sensor 10-Bit Initialization

During PSI5 initialization, the device completes an internal initialization process consisting of the following:

- Power-on Reset
- Device Initialization
- · Program Mode Entry Verification
- · Offset Cancellation Initialization (2 Stages)
- Self-Test

Figure 32 shows the timing for internal and external initialization.

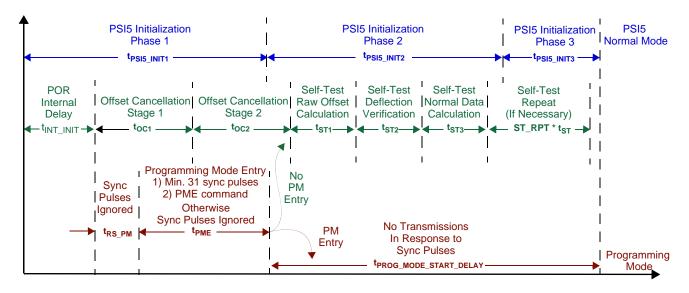


Figure 32. Initialization Timing

4.4.1 PSI5 Initialization Phase 1

During PSI5 initialization phase 1, the device begins internal initialization and self checks, but transmits no data. Initialization begins with the sequence below and shown in Figure 32:

- Internal Delay to ensure analog circuitry has stabilized (t_{INT_INIT})
- Offset Cancellation phase 1 Initialization (t_{OC1})
- Monitor for the Programming Mode Entry Sequence (t_{PME})
 - A sequence of sync pulses received during the program mode entry window in PSI5 initialization phase 1 will allow the device to enter into a PSI5 programming mode if the LOCK_U bit is not set. Reference Section 5.2 for details.
- Offset Cancellation phase 2 Initialization (t_{OC2})
- If the Programming Mode Entry Sequence is not detected, the device enters Initialization Phase 2 (t_{PSI5 INIT2})

4.4.2 PSI5 Initialization Phase 2

During PSI5 initialization phase 2, the device continues it's internal self checks and transmits the PSI5 initialization phase 2 data. The PSI5 initialization data transmission format varies depending on whether the device is programmed for 8-bit or 10-bit data. Initialization is transmitted using the initialization data codes and IDs specified in Table 12, and in the order shown in Figure 33 and Figure 34.

	D1						D2						 D32						
ID1 ₁	$egin{array}{ c c c c c c c c c c c c c c c c c c c$					ID2 ₁	D2 ₁	ID2 ₂	D2 ₂		ID2 _k	D2 _k	 ID32 ₁	D32 ₁	ID32 ₂	D32 ₂		ID32 _k	D32 _k
	Repeat k times					Repeat k times							Rep	eat k ti	mes				

Figure 33. PSI5 Initialization Phase 2 Data Transmission Order (10-bit Mode)

	D1						D2						 D9							
ID1H 1	D1H ₁	ID1H 2	D1H ₂		ID1H k	D1H _k	ID1L 1	D1L ₁	ID1L 2	D1L ₂		ID1L k	D1L _k	 ID9L 1	D9L ₁	ID9L 2	D9L ₂		ID9L k	D9L _k
	Repeat k times						Repeat k times							Rep	eat k ti	mes				

Figure 34. PSI5 Initialization Phase 2 Data Transmission Order (8-bit Mode)

The Initialization phase 2 time is calculated with the following equation:

$$t_{PHASE2} = TRANS_{NIBBLE} \times k \times (DataFields) \times t_{S-S}$$

where:

• TRANS_{NIBBLE} = # of Transmissions per Data Nibble

2 for 10-bit Data: 1 for ID, and 1 for Data 4 for 8-bit Data: 2 for ID, and 2 for Data

• k = the repetition rate for the data fields

Data Fields = 32 data fields for 10-bit data, 9 data fields for 8-bit data

t_{S-S} = Sync Pulse Period

4.4.2.1 PSI5 Initialization Phase 2 (10-Bit Mode)

In PSI5 initialization phase 2, 10-bit mode, the device transmits a sequence of sensor specific configuration and serial number information. The transmission data is in conformance with the PSI5 specification, Revision 1.3 and AKLV27, Revision 1.10. The data content and transmission format is shown in Table 9 and Table 10. Table 9 shows the 10-bit phase 2 timing for different operating modes. Times are calculated using the equation in Section 4.4.2.

Table 9. Initialization Phase 2 Time (10-Bit Mode)

Operating Mode	Repetition Rate (k)	# of Transmissions	Nominal Phase 2 Time
Asynchronous Mode (228 μs)	8	512	116.7 ms
Synchronous Mode (500 μs)	4	256	128.0 ms

Table 10. PSI5 Initialization Phase 2 Data (10-Bit Mode)

PSI5 V1.2 Field ID #	PSI5 V1.2 Nibble ID #	Page Address	PSI5 Nibble Address	Register Address	Description	Value										
F1	D1		0000	Hard-coded	Protocol Revision = V1.3	0100										
F2	D2, D3		0001, 0010	Hard-coded	Number of Data Blocks = 32	0010 0000										
F3	D4, D5		0011, 0100	Hard-coded	Manufacturer = Freescale	0100 0110										
F4	D6, D7		0101, 0110	Hard-coded	Sensor Type = Acceleration (high-g)	0000 0001										
F5	D8		0111	U_DIR[1:0] = 00: 0000 U_DIR[1:0] = 01: 0100 U_DIR[1:0] = 10: 1000 U_DIR[1:0] = 11: 1100 (not used)	Axis	User										
10	D9	0	1000	±60g: 0111 ±120g: 1000 ±240g: 1001 ±480g: 1010	Range	Varies										
F6	D10		1001	DEVCFG2[7:4]	Sensor Specific Information	User										
	D11	•	1010	DEVCFG2[3:0]	Sensor Specific Information	User										
	D12		1011	Hard-coded	Product Revision	0001										
F7	D13	•	1100	Hard-coded	Product Revision	0001										
	D14	•	1101	DEVCFG6[3:0]	Product Revision	User										
	D15		1110	DEVCFG7[7:0], DEVCFG8[4:0]	JY[6:3]	User										
F8	D16	•	1111	converted to	JY[2:0], JM[3]	User										
10	D17		_	0000	Binary coded Julian Date	JM[2:0], JD[1]	User									
	D18														0001	Reference Section 3.1.5.5
	D19		0010	SN0 (High Nibble)	MMA52xx Serial Number	Factory										
	D20	•	0011	SN0 (Low Nibble)	MMA52xx Serial Number	Factory										
	D21	•	0100	SN1 (High Nibble)	MMA52xx Serial Number	Factory										
	D22	•	0101	SN1 (Low Nibble)	MMA52xx Serial Number	Factory										
	D23	•	0110	SN2 (High Nibble)	MMA52xx Serial Number	Factory										
	D24	•	0111	SN2 (Low Nibble)	MMA52xx Serial Number	Factory										
	D25	•	1000	SN3 (High Nibble)	MMA52xx Serial Number	Factory										
	D26		1001	SN3 (Low Nibble)	MMA52xx Serial Number	Factory										
F9	D27	1	1010	Initial Raw Offset (Offset[3:0])	Raw Offset ¹ (If INIT2_EXT=1, '0000' otherwise)	Varies										
	D28		1011	Initial Raw Offset (Offset7:4])	Raw Offset ¹ (If INIT2_EXT=1, '0000' otherwise)	Varies										
	D29		1100	([AvgSelfTest[1:0],Offset[9:8]])	Raw Off/Avg ST ¹ (If INIT2_EXT=1, '0000' otherwise)	Varies										
	D30		1101	Average Self-Test (AvgSelfTest[5:2])	Avg Self-Test ¹ (If INIT2_EXT=1, '0000' otherwise)	Varies										
	D31	D31	Į		-		-				1110	Average Self-Test (AvgSelfTest[9:6])	Avg Self-Test ¹ (If INIT2_EXT=1, '0000' otherwise)	Varies		
	D32		1111	DEVCFG1 [7:4]	Sensor Specific (If INIT2_EXT=1, '0000' otherwise)	0010										

^{1.} Offset and average self-test data will only be transmitted with sync pulse periods that guarantee the self-test phase 1 and phase 2 will be complete prior to required transmission. If sync pulse periods faster than this are used, '0's will be transmitted instead of offset and/or average self-test data.

4.4.2.2 Initialization Phase 2 (8-Bit Mode)

In PSI5 initialization phase 2, 8-bit mode, the device transmits a sequence of sensor specific configuration and serial number information. The transmission data uses a format similar to the PSI5 specification, Revision 1.3 10-Bit format modified for 8-bit transmission. The data content and transmission format is shown in Table 11 and Table 12. Table 11 shows the 8-bit phase 2 timing for different operating modes. Times are calculated using the equation in Section 4.4.2.

Table 11. Initialization Phase 2 Time (8-Bit Mode)

Operating Mode	Repetition Rate (k)	# of Transmissions	Nominal Phase 2 Time
Asynchronous Mode 0 (228 μs)	16	576	131.3 ms
Synchronous Mode (500 μs)	8	288	144.0 ms

Table 12. PSI5 Initialization Phase 2 Data (8-Bit Mode)

PSI5 V1.2 Field ID #	PSI5 V1.2 Nibble ID #	Page Address	PSI5 Half-Nibble Address	Register Address	Description	Value
F1	D1 H	0	00	Hard-coded	Protocol Revision = V1.3	01
F1	D1 L	0	01	Hard-coded	Protocol Revision = V1.3	00
F2	D2 H	0	10	Hard-coded	Number of Data Blocks = 9	00
F2	D2 L	0	11	Hard-coded	Number of Data Blocks = 9	10
F2	D3 H	1	00	Hard-coded	Number of Data Blocks = 9	00
F2	D3 L	1	01	Hard-coded	Number of Data Blocks = 9	00
F3	D4 H	1	10	Hard-coded	Satellite Manufacturer = Freescale	01
F3	D4 L	1	11	Hard-coded	Satellite Manufacturer = Freescale	00
F3	D5 H	2	00	Hard-coded	Satellite Manufacturer = Freescale	01
F3	D5 L	2	01	Hard-coded	Satellite Manufacturer = Freescale	10
F4	D6 H	2	10	Hard-coded	Sensor Type = Acceleration (high-g)	00
F4	D6 L	2	11	Hard-coded	Sensor Type = Acceleration (high-g)	00
F4	D7 H	3	00	Hard-coded	Sensor Type = Acceleration (high-g)	00
F4	D7 L	3	01	Hard-coded	Sensor Type = Acceleration (high-g)	01
F5	D8 H	3	10	U_DIR[1:0] = 00: 0000		User
F5	D8 L	3	11	U_DIR[1:0] = 01: 0100 U_DIR[1:0] = 10: 1000 U_DIR[1:0] = 11: 1100 (not used)	Axis	User
F5	D9 H	4	00	±60g: 0111		Varies
F5	D9 L	4	01	±120g: 1000 ±240g: 1001 ±480g: 1010	Range	Varies

4.4.3 Internal Self-Test

During PSI5 Initialization Phase 2 and Phase 3, the device completes it's internal self-test as described below and shown in Figure 32.

- Self-Test Phase 1 Raw Offset Calculation
 - The average offset is calculated for t_{ST1} (Self-Test Disabled).
 - If the INIT2_EXT bit is set, this 10-bit value is transmitted in Initialization Phase 2 (reference Section 4.4.2).
- · Self-Test Phase 2 Self-Test Deflection Verification
 - The offset cancellation value is frozen for t_{ST2} + 2ms
 - Self-Test is enabled
 - After t_{ST2}/2, the acceleration output value is averaged for t_{ST2}/2 to determine the self-test value
 - If the INIT2_EXT bit is set, this10-bit value is transmitted in Initialization Phase 2 (reference Section 4.4.2).
 - The self-test value is compared against the limits specified in Section 2.5
 - Self-Test is disabled
- · Self-Test Phase 3 Self-Test Normal Data Calculation
 - The average offset is calculated for t_{ST3}
 - If Self-Test passed, the device advances to normal mode
 - If Self-Test failed, the device repeats Self-Test Phases 1 through 3 up to ST_RPT times.

4.4.4 Initialization Phase 3

During PSI5 initialization phase 3, the device completes it's internal self checks, and transmits a combination of "Sensor Busy", "Sensor Ready", or "Sensor Defect" messages as defined in Table 8. The number of messages transmitted in initialization phase 3 varies depending on the mode of operation, and the number of self-test repetitions. Self-Test is repeated on failure up to ST_RPT times to provide immunity to misuse inputs during initialization. Self-Test terminates successfully after one successful self-test sequence.

Table 13 shows the nominal Initialization Phase 3 times for different operating modes and self-test repeats. Times are calculated using the following equation.

$$t_{\text{PSI5INIT3}} = \text{ROUNDUP}\Big(\frac{(t_{\text{INTINIT}} + t_{\text{OC1}} + t_{\text{OC2}} + (t_{\text{ST1}} + t_{\text{ST2}} + t_{\text{ST3}}) \times (\text{STRPT} + 1)) - (t_{\text{PSI5INIT1}} + t_{\text{PSI5INIT2}xx})}{t_{\text{S}-\text{S}}} + 2\Big) \times t_{\text{S}-\text{S}}$$

Table 13. Initialization Phase 3 Time

Operating Mode	Self-Test Repetitions	# of Sensor Busy Messages	# of Sensor Ready or Sensor Defect Messages	Nominal Phase 3 Time (ms)
	0	0		0.46
	1	359		82.31
8-Bit Asynchronous Mode 0 (228 μs)	2	780		178.30
8-Bit Asylictifolious Mode 0 (226 μs)	3	1201		274.28
	4	1622		370.27
	5	2043		466.26
	0	2		0.91
	1	423		96.90
10 Bit Asynchronous Mode 0 (229 us)	2	844		192.89
10-Bit Asynchronous Mode 0 (228 μs)	3	1265		288.88
	4	1686		384.86
	5	2107	2	480.85
	0	0	2	1.00
	1	138		70.00
8-Bit Synchronous Mode (500 μs)	2	330		166.00
o-bit Sylicinorious Mode (500 μs)	3	522		262.00
	4	714		358.00
	5	906		454.00
	0	0		1.00
	1	170		86.00
10-Bit Synchronous Mode (500 μs)	2	362		182.00
To-bit Syricinonous wode (300 μs)	3 554		278.00	
	4	746		374.00
	5	938		470.00

MMA52xxKW

4.5 PSI5 Transmission Modes

4.5.1 Normal Mode

4.5.1.1 Asynchronous Mode

The device can be programmed to respond in asynchronous mode with the following settings:

- TRANS_MD[1:0] = '00' ("Normal Mode")
- ASYNC = '1' in the DEVCFG6 Register
- TIMESLOTA[9:0] = 0x000 in the DEVCFG3 and DEVCFG4 registers

In asynchronous mode, the device transmits data at a fixed rate (t_{ASYNC}) and will not respond to normal sync pulses. However, during initialization phase 1, sync pulses are monitored to decode the Programming Mode Entry Command and allow entry into Programming Mode if the LOCK_U bit is not set.

4.5.1.2 Simultaneous Sampling Mode

The device can be programmed to respond in Simultaneous Sampling Mode by setting the TRANS_MD[1:0] bits to "Normal Mode", and by programming the LATENCY bit to "Simultaneous Sampling Mode".

In Simultaneous Sampling Mode, the most recent interpolated acceleration data sample is latched at t_{TRIG} (rising edge of Sync Pulse) and transmitted starting at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} .

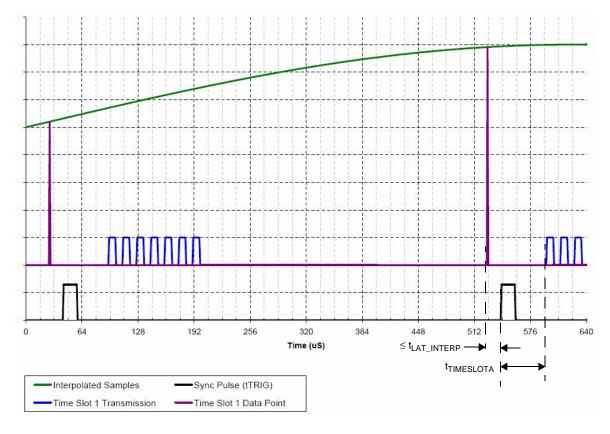


Figure 35. Simultaneous Sampling Mode

4.5.1.3 Synchronous Sampling Mode with Minimum Latency

The device can be programmed to respond in Synchronous Sampling Mode with minimum latency by setting the TRANS_MD[1:0] bits to "Normal Mode", and by programming the LATENCY bit to "Synchronous Sampling Mode".

In Synchronous Sampling Mode, the most recent interpolated acceleration data sample is latched at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} (rising edge of Sync Pulse). The data is transmitted starting at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} .

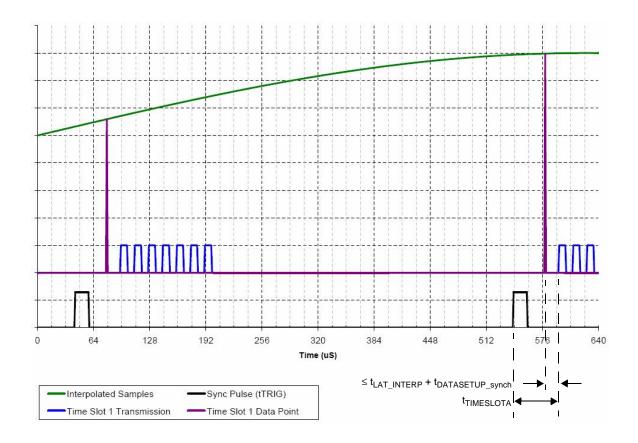


Figure 36. Synchronous Sampling Mode with Minimum Latency

4.5.2 Synchronous Double Sample Rate Mode

The device can be programmed to respond in Synchronous Double Sample Rate Mode with minimum latency by setting the TRANS_MD[1:0] bits to "Synchronous Double Sample Rate Mode". The LATENCY bit does not affect operation in this mode.

In Synchronous Double Sample Rate Mode, the most recent interpolated acceleration data sample is latched at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} (rising edge of Sync Pulse). This data is transmitted starting at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} . In addition, the most recent interpolated acceleration data sample is latched at the time programmed in TIMESLOTB[9:0], relative to t_{TRIG} (rising edge of Sync Pulse) This data is transmitted starting at the time programmed in TIMESLOTB[9:0], relative to t_{TRIG} .

When Synchronous Double Sample Rate Mode is enabled, PSI5 Initialization data is transmitted in both TIMESLOTA[9:0] and TIMESLOTB[9:0]. Identical data is transmitted in both Time slots, including the 10-bit resolution Raw Offset and Self-Test Data in Field 9, D27 though D31 if enabled.

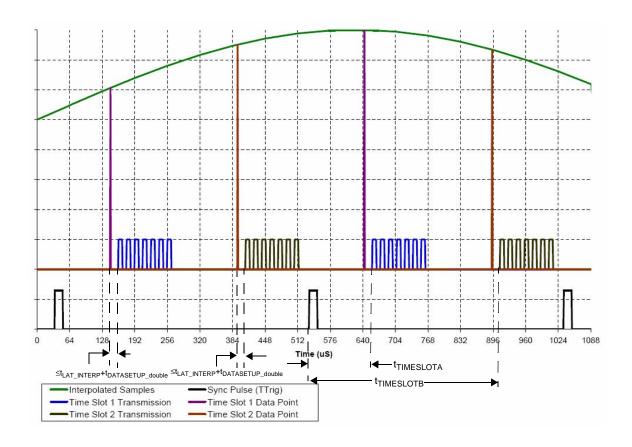


Figure 37. Synchronous Double Sample Rate Mode

Note: In the event that the programmed values in TIMESLOTA[9:0] and TIMESLOTB[9:0] result in a conflict, no data will be transmitted in TIMESLOTB[9:0].

4.5.3 16-Bit Resolution Mode

The device can be programmed to respond in 16-bit Resolution Mode by setting the TRANS_MD[1:0] bits to "16-bit Resolution Mode". In this mode, the 26 bit digital output from the DSP is clipped and scaled to a 16-bit word. Figure 38 shows the method used to establish the 16-bit data word from the 26 bit DSP output.

Ov	Over Range Signal								Noise Margin															
D25	D24	D23	D22	D21	D20	D19	D18	D17	D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5		D2	D1	D0
16	16-bit Data Word D21 D20 D19 D18 D17					D16	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6		Using	g Roui	nding				

Figure 38. 16-Bit Output Scaling Diagram

16-Bit Resolution Mode can be programmed to operate in either "Simultaneous Sampling Mode", or "Synchronous Sampling Mode", by setting the LATENCY bit to the desired operating mode. In Simultaneous Sampling Mode, the most recent interpolated acceleration data sample is latched at t_{TRIG} (rising edge of Sync Pulse). In Synchronous Sampling Mode, the most recent interpolated acceleration data sample is latched at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} (rising edge of Sync Pulse).

The most significant 10 bits (D[21:12]) are truncated and transmitted starting at the time programmed in TIMESLOTA[9:0], relative to t_{TRIG} . The 16-bit value is then clipped to ± 480 counts, and the least significant 10 bits (D15:D6) are transmitted starting at the time programmed in TIMESLOTB[9:0], relative to t_{TRIG} .

When 16-Bit Resolution Mode is enabled, PSI5 Initialization data is transmitted in both TIMESLOTA[9:0] and TIMESLOTB[9:0]. Identical data is transmitted in both Time slots, including the 10-Bit Resolution Raw Offset and Self-Test Data in Field 9, D27 though D31 if enabled.

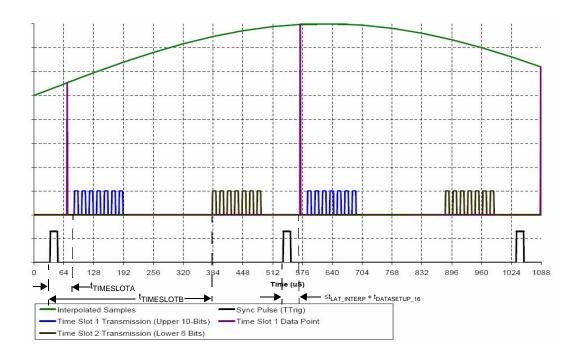


Figure 39. 16-Bit Resolution Mode with Synchronous Sampling

Note: In the event that the programmed values in TIMESLOTA[9:0] and TIMESLOTB[9:0] result in a conflict, no data will be transmitted in TIMESLOTB[9:0].

4.5.4 Daisy Chain Mode

The device can be programmed to operate in Daisy Chain Mode by setting the TRANS_MD[1:0] bits to "Daisy Chain Mode". Daisy Chain Mode can be programmed to operate in either "Simultaneous Sampling Mode", or "Synchronous Sampling Mode" by setting the LATENCY bit to the desired operating mode. In Simultaneous Sampling Mode, the most recent interpolated acceleration data sample is latched at training edge of Sync Pulse). In Synchronous Sampling Mode, the most recent interpolated acceleration data sample is latched at the time programmed in TIMESLOTA[9:0], relative to training edge of Sync Pulse).

When programmed to operate in Daisy Chain Mode, the procedure below is followed:

- On powerup, the device proceeds through normal PSI5 initialization as specified in Section 4.4 using a predefined time slot t_{TIMESLOT DCP}
- Upon successful completion of Initialization Phase 3, including the 2 "Sensor Ready" or Sensor Defect" messages, responses to sync. pulses are terminated and the device waits for a PSI5 "Set Address" command defined in Table 14 and Table 15.
 - The Daisy Chain Programming command and response formats are defined in Section 5.4.
 - Valid Daisy Chain Addresses are defined in Table 16.
 - The response to the PSI5 Set Address command uses the pre-defined time slot t_{TIMESLOT DCP}.
- After receiving a valid address and completing the response, sync. pulses are blanked for t_{DC_BLANKING}. Once
 the blanking time expires, the device does not respond to any sync. pulses until a "Run Mode" command is
 received, as defined in Table 14 and Table 15.
- When the "Run Mode" command is received, the device responds to this command using the programmed daisy
 chain time slot. All commands are then ignored, and sync pulses are responded to with acceleration data using
 the following response format, regardless of the state of the relevant bits in the Device Configuration Registers:

Parameter	Reference	Value
Time Slot	Section 3.1.4.3	Default time slot specified in Table 16
Data Size	Section 3.1.3.5	10-bit data
Error Checking	Section 3.1.3.7	Even Parity
Baud Rate	Section 3.1.3.8	Low Baud Rate: 125 kBaud

During initialization and Run Mode, the Sync pulse pulldown is enabled as specified in Section 3.1.3.3.

Table 14. Daisy Chain Programming Commands and Responses

#	CMD		SAdr			FC		Command	Respo	nse (OK)	Response (Error)			
"	Type	A2	A1	A0	F2	F1	F0	Communa	RC	RD1	RC	RD1		
D0	Short	0	0	0	A2	A1	A0	Set Sensor Address (Daisy Chain)	OK	SAdr	Error	ErrN		
D1	Short	1	1	1	0	0	0	Broadcast Message - "Run Mode"	OK	0x000	Error	ErrN		

Table 15. Daisy Chain Programming Response Code Definitions

Response Code	Definition	Value
RC = OK	Command Message Received Properly	0x1E1
RC = Error	Error during transmission of Command Message	0x1E2
SAdr	Programmed Sensor Address, prepended with 0s	Varies

Table 16. Valid Daisy Chain Addresses

Sen	sor Add (SAdr)		Description	Bus Switch Control	Default Time Slot
A2	A 1	A0			
0	0	0	Address of un-programmed sensor	N/A	N/A
0	0	1	Sensor Address 1	CLOSED	t _{TIMESLOT_DC1}
0	1	0	Sensor Address 2	CLOSED	t _{TIMESLOT_DC2}
0	1	1	Sensor Address 3	CLOSED	t _{TIMESLOT_DC3}
1	0	0	Sensor Address 4	OPEN	t _{TIMESLOT_DC1}
1	0	1	Sensor Address 5	OPEN	t _{TIMESLOT_DC2}
1	1	0	Sensor Address 6	OPEN	t _{TIMESLOT_DC3}
1	1	1	Global Address for Broadcast Message to all Sensors	N/A	N/A

MMA52xxKW

4.6 Error Handling

4.6.1 Sensor Defect Message

The following failures will cause the device to transmit a "Sensor Defect" error message:

Error Condition	Error Type
Offset Error	Temporary (Normal transmissions continue once offset returns within limits)
Self-Test Failure	Latched until reset
IDEN_B, IDEF_B flag cleared	Latched until reset

4.6.2 No Response Error

The following failures will cause the device to stop transmitting:

Error Condition	Error Type
Undervoltage Failure (V _{CC})	Temporary: Normal transmissions continue once voltage returns above failure limit)
Under- / Over-Temperature Failure	Temporary: Normal transmissions continue once temperature returns within the specified limits)

5 Programming Mode Via PSI5

5.1 Introduction

Programming mode via PSI5 is a synchronous communication mode that allows for bidirectional communication with the device. Programming mode is intended for factory programming of the OTP array. It is not intended for use in normal operation.

5.2 Programming Mode Via PSI5 Entry

The device enters programming mode if and only if the following sequence occurs:

- The device is unlocked (the LOCK_U bit in the DEVCFG2 register is '0').
- At least 31 sync pulses are detected, directly preceding the Programming Mode Entry Short Command during the Programming Mode Entry Window shown in Figure 32.
 - The window timing is defined in Section 2.6 (t_{PME}).
 - The Sync pulses and Programming Mode Entry command must be received with a sync pulse period of t_{S-S_PM_L}

If the Programming Mode entry requirement is not met:

- · Programming Mode Entry is blocked until the device is Reset.
- The device proceeds with PSI5 Initialization Phase 2, and PSI5 Initialization Phase 3.
- · The device enters normal mode, and responds as programmed to normal sync pulses.

If the Programming Mode entry requirement is met:

- · Normal transmissions to sync pulses are terminated.
- After a pre-defined Start Delay, the device begins to decode PSI5 Short and Long Commands.
- The device responds only to valid PSI5 Short and Long Commands addressed to Sensor Address '001', as defined in Table 18.

Note: The sync pulse pulldown is disabled in the Programming Mode Entry Window regardless of the state of the SYNCPD bit.

5.3 Programming Mode Via PSI5 - Data Link Layer

5.3.1 Programming Mode Via PSI5 - Command Bit Encoding

Commands messages are transmitted via the modulation of the supply voltage. The presence of a sync pulse is a logic '1' and the absence of a sync pulse is a logic '0'. Sync pulses are expected at a rate of t_{S-S-PM-L}.

5.3.2 Programming Mode Via PSI5 - Command Message Format

Command message data frames consist of a start condition, 3 Start Bits (S[2:0]), a 3 bit Sensor Address (SAdr[2:0]), a 3-bit Function Code (FC[2:0]), an optional Register Address (RAdr[5:0]), an optional data field (D[3:0]), and a 3-bit CRC (C[2:0]. The start condition consists of one of the following:

- 1. A minimum of 5 consecutive logic '0's (with not sync bits)
- 2. A minimum of 31 consecutive logic '1's

The command message format is shown in Figure 41.

S	tart Bit	ts	Sens	sor Add	Iress	Fun	ction C	ode		R	egister	Addre	ss			Da	ata			CRC	
S2	S1	S0	SA0	SA1	SA2	FC0	FC1	FC2	RA0	RA1	RA2	RA3	RA4	RA5	D0	D1	D2	D3	C2	C1	C0
0	1	0	1	0	0	0	1	0	0	0	0	0	0	0	1	1	1	1	0	0	0
																				CRC	
															Data t	o be wri	tten to i	register	(optiona	al)	
									Regist	er Addr	ess (op	tional)									
						Function	on Code	es for M	MA52x	x (Refer	ence S	ection 5	.3.6)								
			Senso	r Addre	ss - Fix	ed at 00	1 for M	MA52xx	(
Start B	Bit Sequ	ence =	010																		

Figure 40. Programming Mode Via PSI5 Command Data Format

Bit stuffing is necessary to maintain a synchronized time base between the command master and the device. A logic '1' Sync bit is added every 4th bit in the command message to ensure there will never be more than 3 logic '0' bits in a row.

St	art B	its			Senso ddres			Fund	tion (Code			F	Regist	er A	ddres	s					Data	ı			CF	C	
S2	S1	S0	Sy	SA0	SA1	SA2	Sy	FC0	FC1	FC2	Sy	RA0	RA1	RA2	Sy	RA3	RA4	RA5	Sy	D0	D1	D2	Sy	D3	C2	C1	Sy	C0
0	1	0	1	1	0	0	1	0	0	0	1	0	0	0	1	0	0	0	1	1	1	1	1	1	0	0	1	0

1	Response	•
RC	RD1	RD0
\$1E2	\$3FF	\$3FF

Response RD1 RD0

\$3FF \$3FF

Figure 41. Programming Mode Via PSI5 Command Data Format with Sync Bits

Once a command is received and verified, the device expects 2 to 3 consecutive sync pulses (depending upon the command message lengths described below). For each of these sync pulses, the device will respond with the following settings:

Parameter	Register Bits	Reference	Value
Time Slot	N/A	N/A	t _{TIMESLOT_DC1}
Data Size	DATASIZE = 0	Section 3.1.3.5	10-bit data
Error Checking	P_CRC = 0	Section 3.1.3.7	Even Parity
Baud Rate	BAUD	Section 3.1.3.8	125 kBaud
Sync Pulse Pulldown	SYNCPD	Section 3.1.3.3	Disabled

Figure 42. Programming Mode Via PSI5 Response Message Settings

5.3.2.1 **Short Frame Command and Response Format**

Short frames are the simplest type of command message. No data is transmitted in a short frame command. Only specific instructions are performed in response to short frame commands. The Short Frame format is shown in Figure 43. Short Frame commands and responses are defined in Section 5.3.6. Table 18.

St	art Bi	its			Senso ddres			Fund	tion (Code			CRC	
S2	S1	S0	Sy	SA0	SA1	SA2	Sy	FC0	FC1	FC2	Sy	C2	C1	C0
0	1	0	1	1	0	0	1	0	0	1	1	0	0	0

Figure 43. Programming Mode Via PSI5 Short Command and Response Format

5.3.2.2 **Long Frame Command and Response Format**

Long frames allow for the transmission of data nibbles for register writes. The device can provide register data in response to a read or write request. The Long Frame format is shown in Figure 44. Long Frame commands and responses are defined in Section 5.3.6.

St	art E	Bits			Senso ddres			Fund	tion (Code			F	Regist	er A	ddres	s					Data				CF	C	
S2	S1	S0	Sy	SA0	SA1	SA2	Sy	FC0	FC1	FC2	Sy	RA0	RA1	RA2	Sy	RA3	RA4	RA5	Sy	D0	D1	D2	Sy	D3	C2	C1	Sy	C0
0	1	0	1	1	0	0	1	0	1	0	1	0	0	0	1	0	0	0	1	1	1	1	1	1	0	0	1	0



Response RC

\$1E2

RD1

\$3FF

Figure 44. Programming Mode Via PSI5 Long Command and Response Format

5.3.3 Command Message CRC

Programming mode command error checking is accomplished by a 3-bit CRC. The 3-bit CRC is calculated using all message bits except start bits and sync bits. The CRC verification uses a generator polynomial of $g(x) = X^3 + X + 1$, with a seed value = '111'. The data is provided to the CRC calculator in the order received (LSB first, SAdr, FC, RAdr, Data), and then augmented with three '0's. Table 8 shows some example CRC calculation values for 10-bit data transmissions.

The calculated CRC is then compared against the received 3-bit CRC (received MSB first). If a CRC mismatch is detected, the device responds with a CRC Error response as defined in Section 5.3.7.

5.3.4 Command Sync Pulse Blanking Time

In Programming Mode and Programming Mode Entry, the device employs a fixed Sync Pulse blanking time of t_{SYNC_OFF_500} regardless of the state of the BLANKTIME bit.

5.3.5 Command Timeout

In the event that the device does not detect a sync pulse within a 4-bit window time (missing sync bit), the command reception will be terminated and the device will respond to the next sync pulse with a Short Frame Framing Error response as defined in Section 5.3.7.

5.3.6 Programming Mode Via PSI5 Command and Response Summary

Table 17. Programming Mode Via PSI5 Commands and Responses

#	CMD	SAdr	FC	Command	Regis-	Data		Response (OK)	R	esponse (E	rror)
#	Type	SAUI	FC	Command	ter Address	Field	RC	RD1	RD0	RC	RD1	RD0
S0	Short		100	Execute Programming of NVM	N/A	N/A	OK	0x2AA	N/A	Error	ErrN	N/A
S1	Short		101	Invalid Command	N/A	N/A		No Respor	nse		No Respor	nse
S2	Short		110	Invalid Command	N/A	N/A		No Respor	nse		No Respor	nse
S3	Short		111	Enter Programming Mode	N/A	N/A	OK	0x0CA	N/A		No Respor	nse
LR	Long	001	010	Read nibble located at address RA5:RA0	Varies	Varies	ОК	RData	RData+1	Error	ErrN	0x000
LW	Long		011	Write nibble to register RA5:RA0	Varies	Varies	OK	WData	RA5:RA0	Error	ErrN	0x000
XLR	XLong		000	Invalid Command	Any	Any		No Respor	nse		No Respor	nse
XLW	XLong		001	Invalid Command	Any	Any		No Respor	nse		No Respor	nse

Note: When reading the last address in the data array, RData+1 will always return 0x00.

Table 18. Programming Mode Via PSI5 Response Code Definitions

Response Code	Definition	Value
RC = OK	Command Message Received Properly	0x1E1
RC = Error	Error during transmission of Command Message	0x1E2
RData	Byte Contents of Register located at Byte address in which nibble address RA5:RA0 falls in. (Example: For RA5:RA0 = \$04 - RData = Data at Byte Address \$02)	Varies
RData + 1	Byte Contents of Register located at Byte address in which nibble address RA5:RA0 +2 falls in. (Example: For RA5:RA0 = \$04 - RData + 1= Data at Byte Address \$03)	Varies
WData	Byte Contents of Register located at Byte address in which nibble address RA5:RA0 falls in after write operation. (Example: For RA5:RA0 = \$04 - RData = Data at Byte Address \$02)	Varies

5.3.7 Programming Mode Via PSI5 Error Response Summary

Table 19. Error Response Summary

ErrN*	Mnemonic	Description	Supported By MMA52xx
0000	General	General Error	No
0001	Framing	Framing Error	Yes
0010	CRC	CRC Error on Received Message	Yes
0011	Address	Sensor Address Not Supported	No (Invalid Address is ignored)
0100	FC	Function Code Not Supported	No (N/A)
0101	Data Range	Unsupported Register Address	Yes
0110	Write Protect	Destination Address is Write protected (Locked)	Yes
0111	Reserved	Reserved	No
1000			
1001	7		
1010	7		
1011	Decembed 1	Desamined	No.
1100	Reserved	Reserved	No
1101			
1110	7		
1111	7		

^{*} ErrN is transmitted in the 4 LSBs of RD1. All other bits in the response data field are set to '0'.

5.4 OTP Programming Via PSI5 Procedure

- 1. Enter Programming Mode.
- 2. Load desired data into the OTP shadow registers using PSI5 Long Write commands.
- 3. Send "Execute Programming of NVM "Short command.
- 4. Set V_{CC} = V_{PP} prior to, or within t_{PROG_HOLD} after the response to the "Execute Programming of NVM" Command has been received. There is an internal delay of t_{PROG_DELAY} after the "Execute Programming of NVM" Command is received until the OTP programming begins.
 - a. OTP write time depends on the number of bits being written to '1'. Each bit that is programmed requires t_{PROG BIT}.
 - b. During the OTP Write sequence, sync pulses will be ignored. However, transmission of sync pulses during the OTP Write sequence should be prevented.
- 5. Read the SC register and verify IDEF_B flag is set (indicating the write is complete and successful, and the shadow registers have been refreshed with the OTP contents).
- 6. Read the OTP register values and compare to the desired values.

6 Package

6.1 Case Outline Drawing

Reference Freescale Case Outline Drawing # 98ASA00090D

http://www.freescale.com/files/shared/doc/package_info/98ASA00090D.pdf

6.2 Recommended Footprint

Reference Freescale Application Note AN3111, latest revision:

http://www.freescale.com/files/sensors/doc/app_note/AN3111.pdf

Table 20. Revision History

Revision number	Revision date	Description of changes
9	03/2012	 Added SafeAssure logo, changed first paragraph and disclaimer to include trademark information. Section 3.1.2.1: Removed Axis column in table.

How to Reach Us:

Home Page:

www.freescale.com

Web Support:

http://www.freescale.com/support

USA/Europe or Locations Not Listed:

Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
1-800-521-6274 or +1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH Technical Information Center Schatzbogen 7 81829 Muenchen, Germany +44 1296 380 456 (English) +46 8 52200080 (English) +49 89 92103 559 (German) +33 1 69 35 48 48 (French) www.freescale.com/support

Japan:

Freescale Semiconductor Japan Ltd. Headquarters ARCO Tower 15F 1-8-1, Shimo-Meguro, Meguro-ku, Tokyo 153-0064 Japan 0120 191014 or +81 3 5437 9125 support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor China Ltd. Exchange Building 23F No. 118 Jianguo Road Chaoyang District Beijing 100022 China +86 10 5879 8000 support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center 1-800-441-2447 or +1-303-675-2140 Fax: +1-303-675-2150 LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale and the Freescale logo are trademarks of Freescale Semiconductor, Inc., Reg. U.S. Pat. & Tm. Off. SafeAssure and Xtrinsic are trademarks of Freescale Semiconductor. Inc.

All other product or service names are the property of their respective owners. © 2012 Freescale Semiconductor, Inc. All rights reserved.

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see http://www.freescale.com or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to http://www.freescale.com/epp.

